



AMC1106x 小型で高精度の基本絶縁型デルタ-シグマ変調器

1 特長

- ・ シャント抵抗を用いた電流測定用に最適化された、 $\pm 50\text{mV}$ の入力電圧範囲
- ・ マンチェスター符号化または非符号化のビットストリーム・オプション
- ・ 優れたDC性能により、システム・レベルで高精度のセンシングを実現:
 - オフセット誤差およびドリフト: $\pm 50\mu\text{V}$ 、 $\pm 1\mu\text{V}/^\circ\text{C}$ (最大値)
 - ゲイン誤差およびドリフト: $\pm 0.2\%$ 、 $\pm 40\text{ppm}/^\circ\text{C}$ (最大値)
- ・ 3.3Vで動作し、絶縁膜の両側で消費電力を削減
- ・ システム・レベル診断機能
- ・ 高い電磁界耐性
(『ISO72x デジタル・アイソレータ磁界耐性』アプリケーション・レポートを参照)
- ・ 安全関連の認定:
 - DIN V VDE V 0884-11 (VDE V 0884-11): 2017-01に準拠した5657V_{PK}の基本絶縁
 - UL1577に準拠した絶縁耐圧: 4000V_{RMS} (1分間)
 - CAN/CSA No.5A-Component Acceptance Service Notice、IEC 60950-1、およびIEC 60065 End Equipment Standards認定

2 アプリケーション

三相電気メータにおけるシャント抵抗ベースの電流センシング

3 概要

AMC1106は高精度のデルタ・シグマ($\Delta\Sigma$)変調器で、磁気干渉に対して高い耐性のある静電容量性絶縁膜により、入力と出力の回路が分離されています。

AMC1106の入力段は、多相電気メータによく採用されるシャント抵抗やその他の低電圧レベルの信号源と直接接続するように最適化されており、優れたACおよびDC性能を実現します。 $\pm 50\text{mV}$ という低い入力電圧範囲により、シャント抵抗値を小さくして消費電力を最小限に抑えることができます。AMC1106の出力ビットストリームは、適切なデジタル・フィルタを使用して間引くことができます。

MSP430F67x、TMS320F2807x、およびTMS320F2837xマイクロコントローラ、ならびにAMC1210には、こうしたデジタル・フィルタが内蔵されているため、AMC1106を使用した場合にシームレスに動作します。

ハイサイドでは、この変調器は3.3Vまたは5V電源(AVDD)から電源を供給されます。絶縁デジタル・インターフェイスは、3.0V、3.3V、5Vの電源(DVDD)で動作します。

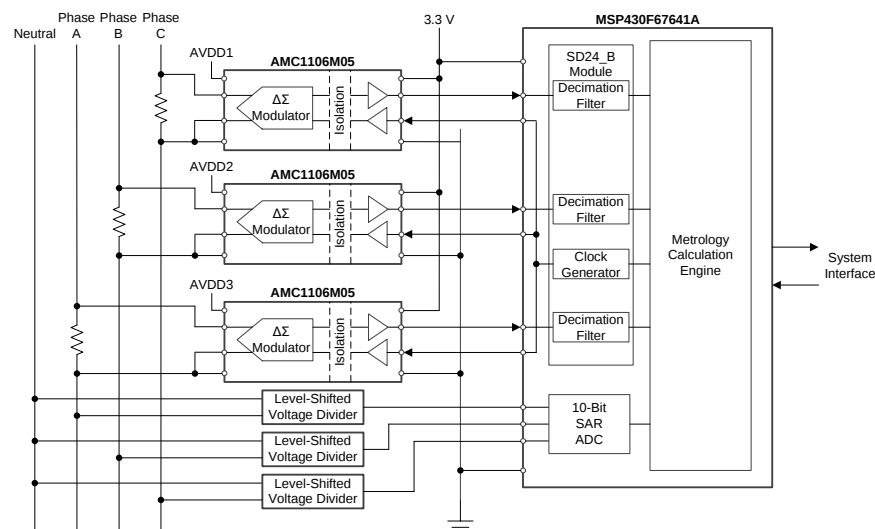
AMC1106は、 -40°C ～ $+125^\circ\text{C}$ の拡張工業用温度範囲で仕様が規定されています。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
AMC1106x	SOIC (8)	5.85mm×7.50mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

概略回路図



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4 改訂履歴

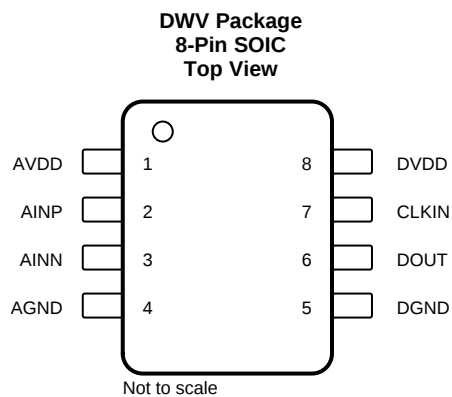
資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

2017年10月発行のものから更新	Page
• Changed test conditions of DTI parameter	5
• Changed test conditions of V_{IOSM} parameter	5
• Changed test conditions of second q_{pd} parameter row	5
• Changed test conditions of third q_{pd} parameter row	5
• Changed VDE certification details in <i>Safety Related Certifications</i> table	6
• Changed <i>Block Diagram of an Isolation Channel</i> figure	20

5 Device Comparison Table

PART NUMBER	DIGITAL OUTPUT INTERFACE
AMC1106E05	Manchester coded CMOS
AMC1106M05	Uncoded CMOS

6 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	AVDD	—	Analog (high-side) power supply, 3.0 V to 5.5 V. See the Power Supply Recommendations section for decoupling recommendations.
2	AINP	I	Noninverting analog input
3	AINN	I	Inverting analog input
4	AGND	—	Analog (high-side) ground reference
5	DGND	—	Digital (controller-side) ground reference
6	DOUT	O	Modulator data output. This pin is a Manchester coded output for the AMC1106E05.
7	CLKIN	I	Modulator clock input
8	DVDD	—	Digital (controller-side) power supply, 2.7 V to 5.5 V. See the Power Supply Recommendations section for decoupling recommendations.

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾

	MIN	MAX	UNIT
Supply voltage, AVDD to AGND or DVDD to DGND	–0.3	6.5	V
Analog input voltage at AINP, AINN	AGND – 6	AVDD + 0.5	V
Digital output voltage at DOUT, or digital input voltage on CLKIN	DGND – 0.5	DVDD + 0.5	V
Input current to any pin except supply pins	–10	10	mA
Junction temperature, T _J		150	°C
Storage temperature, T _{stg}	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

	VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
AVDD Analog (high-side) supply voltage (AVDD to AGND)	3.0	5.0	5.5	V
DVDD Digital (controller-side) supply voltage (DVDD to DGND)	2.7	3.3	5.5	V
T _A Operating ambient temperature	–40		125	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾	AMC1106x	UNIT
	DWV (SOIC)	
	8 PINS	
R _{θJA} Junction-to-ambient thermal resistance	112.2	°C/W
R _{θJC(top)} Junction-to-case (top) thermal resistance	47.6	°C/W
R _{θJB} Junction-to-board thermal resistance	60.0	°C/W
ψ _{JT} Junction-to-top characterization parameter	23.1	°C/W
ψ _{JB} Junction-to-board characterization parameter	60.0	°C/W
R _{θJC(bot)} Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Power Ratings

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
P _D Maximum power dissipation (both sides)	AMC1106E05, AVDD = DVDD = 5.5 V			91.85	mW
	AMC1106M05, AVDD = DVDD = 5.5 V			86.90	
P _{D1} Maximum power dissipation (high-side supply)	AVDD = 5.5 V			53.90	mW
P _{D2} Maximum power dissipation (low-side supply)	AMC1106E05, AVDD = DVDD = 5.5 V			37.95	mW
	AMC1106M05, AVDD = DVDD = 5.5 V			33.00	

7.6 Insulation Specifications

over operating ambient temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	VALUE	UNIT
GENERAL				
CLR	External clearance ⁽¹⁾	Shortest pin-to-pin distance through air	≥ 9	mm
CPG	External creepage ⁽¹⁾	Shortest pin-to-pin distance across the package surface	≥ 9	mm
DTI	Distance through insulation	Minimum internal gap (internal clearance) of the insulation	≥ 0.021	mm
CTI	Comparative tracking index	DIN EN 60112 (VDE 0303-11); IEC 60112	≥ 600	V
	Material group	According to IEC 60664-1	I	
	Overvoltage category per IEC 60664-1	Rated mains voltage ≤ 300 V _{RMS}	I-IV	
		Rated mains voltage ≤ 600 V _{RMS}	I-IV	
DIN V VDE V 0884-11 (VDE V 0884-11): 2017-01 ⁽²⁾				
V _{IORM}	Maximum repetitive peak isolation voltage	At ac voltage (bipolar)	849	V _{PK}
V _{IOWM}	Maximum-rated isolation working voltage	At ac voltage (sine wave)	600	V _{RMS}
		At dc voltage	849	V _{DC}
V _{IOTM}	Maximum transient isolation voltage	V _{TEST} = V _{IOTM} , t = 60 s (qualification test)	5657	V _{PK}
		V _{TEST} = 1.2 × V _{IOTM} , t = 1 s (100% production test)	6789	
V _{IOSM}	Maximum surge isolation voltage ⁽³⁾	Test method per IEC 60065, 1.2/50-μs waveform, V _{TEST} = 1.3 × V _{IOSM} = 7800 V _{PK} (qualification)	6000	V _{PK}
q _{pd}	Apparent charge ⁽⁴⁾	Method a, after input/output safety test subgroup 2 / 3, V _{ini} = V _{IOTM} , t _{ini} = 60 s, V _{pd(m)} = 1.2 × V _{IORM} = 1019 V _{PK} , t _m = 10 s	≤ 5	pC
		Method a, after environmental tests subgroup 1, V _{ini} = V _{IOTM} , t _{ini} = 60 s, V _{pd(m)} = 1.3 × V _{IORM} = 1104 V _{PK} , t _m = 10 s	≤ 5	
		Method b1, at routine test (100% production) and preconditioning (type test), V _{ini} = V _{IOTM} , t _{ini} = 1 s, V _{pd(m)} = 1.5 × V _{IORM} = 1274 V _{PK} , t _m = 1 s	≤ 5	
C _{IO}	Barrier capacitance, input to output ⁽⁵⁾	V _{IO} = 0.5 V _{PP} at 1 MHz	1.2	pF
R _{IO}	Insulation resistance, input to output ⁽⁵⁾	V _{IO} = 500 V at T _S = 150°C	> 10 ⁹	Ω
	Pollution degree		2	
	Climatic category		40/125/21	
UL1577				
V _{ISO}	Withstand isolation voltage	V _{TEST} = V _{ISO} = 4000 V _{RMS} or 5657 V _{DC} , t = 60 s (qualification), V _{TEST} = 1.2 × V _{ISO} = 4800 V _{RMS} , t = 1 s (100% production test)	4000	V _{RMS}

- (1) Apply creepage and clearance requirements according to the specific equipment isolation standards of an application. Care must be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed circuit board (PCB) do not reduce this distance. Creepage and clearance on a PCB become equal in certain cases. Techniques such as inserting grooves and ribs on the PCB are used to help increase these specifications.
- (2) This coupler is suitable for *safe electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Testing is carried out in air or oil to determine the intrinsic surge immunity of the isolation barrier.
- (4) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (5) All pins on each side of the barrier are tied together, creating a two-pin device.

7.7 Safety-Related Certifications

VDE	UL
Certified according to DIN V VDE V 0884-11 (VDE V 0884-11): 2017-01, DIN EN60950-1 (VDE 0805 Teil 1): 2014-08, and DIN EN 60065 (VDE 0860): 2005-11	Recognized under 1577 component recognition and CSA component acceptance NO 5 programs
Basic insulation	Single protection
Certificate number: 40047657	File number: E181974

7.8 Safety Limiting Values

Safety limiting intends to minimize potential damage to the isolation barrier upon failure of input or output (I/O) circuitry. A failure of the I/O may allow low resistance to ground or the supply and, without current limiting, dissipate sufficient power to overheat the die and damage the isolation barrier, potentially leading to secondary system failures.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _S Safety input, output, or supply current, see Figure 3	$\theta_{JA} = 112.2^{\circ}\text{C/W}$, VDD1 = VDD2 = 5.5 V, T _J = 150°C, T _A = 25°C			202.5	mA
	$\theta_{JA} = 112.2^{\circ}\text{C/W}$, VDD1 = VDD2 = 3.6 V, T _J = 150°C, T _A = 25°C			309.4	
P _S Safety input, output, or total power, see Figure 4	$\theta_{JA} = 112.2^{\circ}\text{C/W}$, T _J = 150°C, T _A = 25°C			1114 ⁽¹⁾	mW
T _S Maximum safety temperature				150	°C

(1) Input, output, or the sum of input and output power must not exceed this value.

The maximum safety temperature is the maximum junction temperature specified for the device. The power dissipation and junction-to-air thermal impedance of the device installed in the application hardware determines the junction temperature. The assumed junction-to-air thermal resistance in the [Thermal Information](#) table is that of a device installed on a high-K test board for leaded surface-mount packages. The power is the recommended maximum input voltage times the current. The junction temperature is then the ambient temperature plus the power times the junction-to-air thermal resistance.

7.9 Electrical Characteristics: AMC1106x

minimum and maximum specifications apply from $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $\text{AVDD} = 3.0\text{ V}$ to 5.5 V , $\text{DVDD} = 2.7\text{ V}$ to 5.5 V , $\text{AINP} = -50\text{ mV}$ to 50 mV , $\text{AINN} = \text{AGND}$, and sinc^3 filter with $\text{OSR} = 256$ (unless otherwise noted); typical specifications are at $T_A = 25^{\circ}\text{C}$, $\text{CLKIN} = 20\text{ MHz}$, $\text{AVDD} = 5\text{ V}$, and $\text{DVDD} = 3.3\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUTS						
V _{Clipping}	Differential input voltage before clipping output	V _{IN} = AINP – AINN	±64			mV
FSR	Specified linear differential full-scale	V _{IN} = AINP – AINN	–50		50	mV
	Absolute common-mode input voltage ⁽¹⁾	(AINP + AINN) / 2 to AGND	–2		AVDD	V
V _{CM}	Operating common-mode input voltage	(AINP + AINN) / 2 to AGND	–0.032		AVDD – 2.1	V
V _{CMov}	Common-mode overvoltage detection level ⁽²⁾	(AINP + AINN) / 2 to AGND	AVDD – 2			V
C _{IN}	Single-ended input capacitance	AINN = AGND		4		pF
C _{IND}	Differential input capacitance			2		pF
I _{IB}	Input bias current	AINP = AINN = AGND, I _{IB} = I _{IBP} + I _{IBN}	–97	–72	–57	μA
R _{IN}	Single-ended input resistance	AINN = AGND		4.75		kΩ
R _{IND}	Differential input resistance			4.9		kΩ
I _{IO}	Input offset current			±10		nA
CMTI	Common-mode transient immunity		15			kV/μs
CMRR	Common-mode rejection ratio	AINP = AINN, f _{IN} = 0 Hz, V _{CM min} ≤ V _{IN} ≤ V _{CM max}		–99		dB
		AINP = AINN, f _{IN} from 0.1 Hz to 50 kHz, V _{CM min} ≤ V _{IN} ≤ V _{CM max}		–98		
BW	Input bandwidth ⁽³⁾			800		kHz
DC ACCURACY						
DNL	Differential nonlinearity	Resolution: 16 bits	–0.99		0.99	LSB
INL	Integral nonlinearity ⁽⁴⁾	Resolution: 16 bits, 4.5 V ≤ AVDD ≤ 5.5 V	–4	±1	4	LSB
		Resolution: 16 bits, 3.0 V ≤ AVDD ≤ 3.6 V	–5	±1.5	5	
E _O	Offset error	Initial, at 25°C, AINP = AINN = AGND	–50	±2.5	50	μV
TCE _O	Offset error thermal drift ⁽⁵⁾		–1	±0.25	1	μV/°C
E _G	Gain error	Initial, at 25°C	–0.2%	±0.005%	0.2%	
TCE _G	Gain error thermal drift ⁽⁶⁾		–40	±20	40	ppm/°C
PSRR	Power-supply rejection ratio	AINP = AINN = AGND, 3.0 V ≤ AVDD ≤ 5.5 V, at dc		–108		dB
		AINP = AINN = AGND, 3.0 V ≤ AVDD ≤ 5.5 V, 10 kHz, 100-mV ripple		–107		
AC ACCURACY						
SNR	Signal-to-noise ratio	f _{IN} = 1 kHz	78	82.5		dB
SINAD	Signal-to-noise + distortion	f _{IN} = 1 kHz	77.5	82.3		dB
THD	Total harmonic distortion	4.5 V ≤ AVDD ≤ 5.5 V, 5 MHz ≤ f _{CLKIN} ≤ 21 MHz, f _{IN} = 1 kHz		–98	–84	dB
		3.0 V ≤ AVDD ≤ 3.6 V, 5 MHz ≤ f _{CLKIN} ≤ 20 MHz, f _{IN} = 1 kHz		–93	–83	
SFDR	Spurious-free dynamic range	f _{IN} = 1 kHz	83	100		dB

(1) Steady-state voltage supported by the device in case of a system failure. See the specified common-mode input voltage V_{CM} for normal operation. Observe the analog input voltage range as specified in the [Absolute Maximum Ratings](#) table.

(2) The common-mode overvoltage detection level has a typical hysteresis of 90 mV.

(3) This parameter is the -3-dB, second-order, roll-off frequency of the integrated differential input amplifier to consider for antialiasing filter designs.

(4) Integral nonlinearity is defined as the maximum deviation from a straight line passing through the end-points of the ideal ADC transfer function expressed as a number of LSBs or as a percent of the specified linear full-scale range (FSR).

(5) Offset error drift is calculated using the box method, as described by the following equation:

$$\text{TCE}_{\text{O}} = \frac{\text{value}_{\text{MAX}} - \text{value}_{\text{MIN}}}{\text{TempRange}}$$

(6) Gain error drift is calculated using the box method, as described by the following equation:

$$\text{TCE}_{\text{G}} (\text{ppm}) = \left(\frac{\text{value}_{\text{MAX}} - \text{value}_{\text{MIN}}}{\text{value} \times \text{TempRange}} \right) \times 10^6$$

AMC1106E05, AMC1106M05

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Electrical Characteristics: AMC1106x (continued)

minimum and maximum specifications apply from $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $\text{AVDD} = 3.0\text{ V}$ to 5.5 V , $\text{DVDD} = 2.7\text{ V}$ to 5.5 V , $\text{AINP} = -50\text{ mV}$ to 50 mV , $\text{AINN} = \text{AGND}$, and sinc³ filter with $\text{OSR} = 256$ (unless otherwise noted); typical specifications are at $T_A = 25^{\circ}\text{C}$, $\text{CLKIN} = 20\text{ MHz}$, $\text{AVDD} = 5\text{ V}$, and $\text{DVDD} = 3.3\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DIGITAL INPUTS/OUTPUTS (CMOS Logic With Schmitt-Trigger)						
I _{IN}	Input current	DGND ≤ V _{CLKIN} ≤ DVDD	0		7	μA
C _{IN}	Input capacitance			4		pF
V _{IH}	High-level input voltage		0.7 × DVDD		DVDD + 0.3	V
V _{IL}	Low-level input voltage		−0.3		0.3 × DVDD	V
V _{OH}	High-level output voltage	I _{OH} = −20 μA	DVDD − 0.1			V
		I _{OH} = −4 mA	DVDD − 0.4			
V _{OL}	Low-level output voltage	I _{OL} = 20 μA	0.1			V
		I _{OL} = 4 mA	0.4			
C _{LOAD}	Output load capacitance			30		pF
POWER SUPPLY						
I _{AVDD}	High-side supply current	3.0 V ≤ AVDD ≤ 3.6 V		6.3	8.5	mA
		4.5 V ≤ AVDD ≤ 5.5 V		7.2	9.8	
I _{DVDD}	Controller-side supply current	AMC1106E05, 2.7 V ≤ DVDD ≤ 3.6 V, C _{LOAD} = 15 pF		4.1	5.5	mA
		AMC1106M05, 2.7 V ≤ DVDD ≤ 3.6 V, C _{LOAD} = 15 pF		3.3	4.8	
		AMC1106E05, 4.5 V ≤ DVDD ≤ 5.5 V, C _{LOAD} = 15 pF		5.0	6.9	
		AMC1106M05, 4.5 V ≤ DVDD ≤ 5.5 V, C _{LOAD} = 15 pF		3.9	6.0	

7.10 Timing Requirements

over operating ambient temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
f_{CLKIN}	CLKIN clock frequency	$4.5\text{ V} \leq \text{AVDD} \leq 5.5\text{ V}$	5		21	MHz
		$3.0\text{ V} \leq \text{AVDD} \leq 5.5\text{ V}$	5		20	
t_{CLKIN}	CLKIN clock period, see Figure 1	$4.5\text{ V} \leq \text{AVDD} \leq 5.5\text{ V}$	47.6		200	ns
		$3.0\text{ V} \leq \text{AVDD} \leq 5.5\text{ V}$	50		200	
t_{HIGH}	CLKIN clock high time, see Figure 1		20	25	120	ns
t_{LOW}	CLKIN clock low time, see Figure 1		20	25	120	ns

7.11 Switching Characteristics

over operating ambient temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{H}	DOUT hold time after rising edge of CLKIN, see Figure 1	AMC1106M05 ⁽¹⁾ , $C_{\text{LOAD}} = 15\text{ pF}$	3.5		ns
t_{D}	Rising edge of CLKIN to DOUT valid delay, see Figure 1	AMC1106M05 ⁽¹⁾ , $C_{\text{LOAD}} = 15\text{ pF}$		15	ns
t_{r}	DOUT rise time, see Figure 1	10% to 90%, $2.7\text{ V} \leq \text{DVDD} \leq 3.6\text{ V}$, $C_{\text{LOAD}} = 15\text{ pF}$	0.8	3.5	ns
		10% to 90%, $4.5\text{ V} \leq \text{DVDD} \leq 5.5\text{ V}$, $C_{\text{LOAD}} = 15\text{ pF}$	1.8	3.9	
t_{f}	DOUT fall time, see Figure 1	90% to 10%, $2.7\text{ V} \leq \text{DVDD} \leq 3.6\text{ V}$, $C_{\text{LOAD}} = 15\text{ pF}$	0.8	3.5	ns
		90% to 10%, $4.5\text{ V} \leq \text{DVDD} \leq 5.5\text{ V}$, $C_{\text{LOAD}} = 15\text{ pF}$	1.8	3.9	
t_{START}	Interface startup time, see Figure 2	DVDD at 2.7 V (min) to DOUT valid with $\text{AVDD} \geq 3.0\text{ V}$	32	32	t_{CLKIN}
t_{ASTART}	Analog startup time, see Figure 2	AVDD step to 3.0 V with DVDD $\geq 2.7\text{ V}$, 0.1% settling	0.5		ms

- (1) The output of the Manchester encoded versions of the AMC1106E05 can change with every edge of CLKIN with a typical delay of 6 ns; see the [Manchester Coding Feature](#) section for additional details.

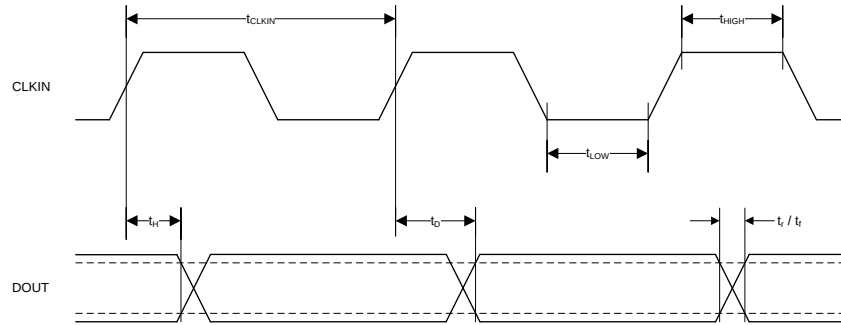


Figure 1. Digital Interface Timing

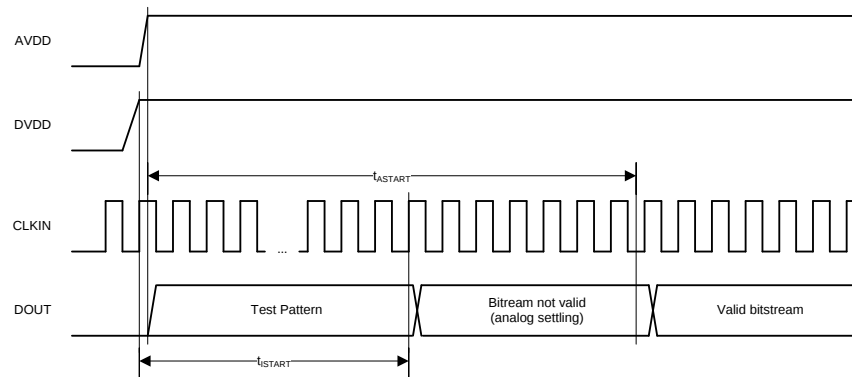


Figure 2. Device Startup Timing

7.12 Insulation Characteristics Curves

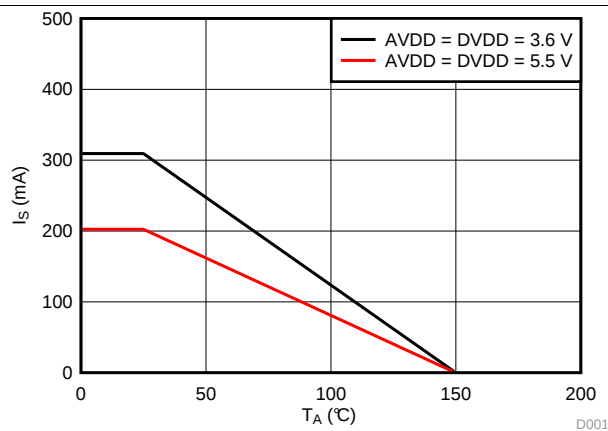


Figure 3. Thermal Derating Curve for Safety-Limiting Current per VDE

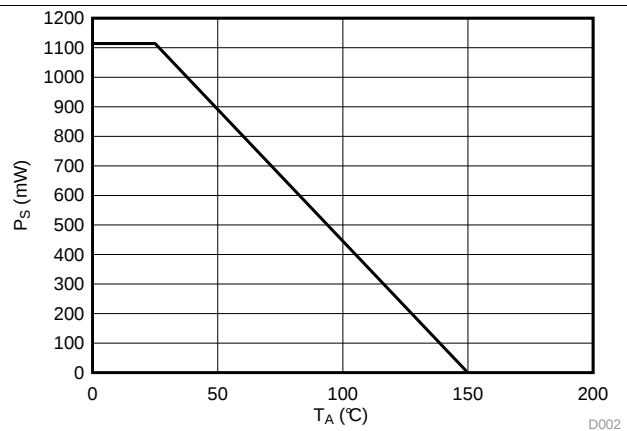


Figure 4. Thermal Derating Curve for Safety-Limiting Power per VDE

7.13 Typical Characteristics

at $T_A = 25^\circ\text{C}$, $AVDD = 5\text{ V}$, $DVDD = 3.3\text{ V}$, $AINP = -50\text{ mV}$ to 50 mV , $AINN = AGND$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with $OSR = 256$ (unless otherwise noted)

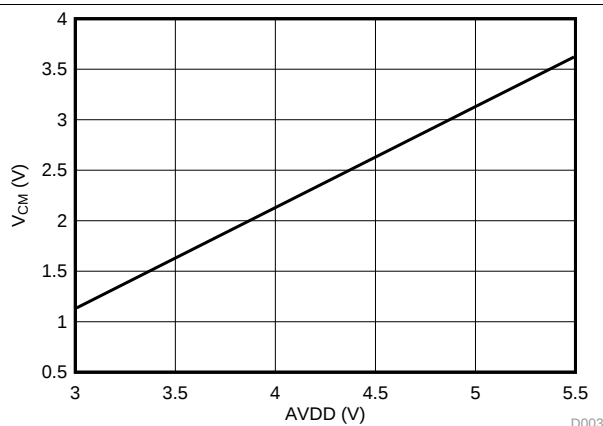


Figure 5. Maximum Operating Common-Mode Input Voltage vs High-Side Supply Voltage

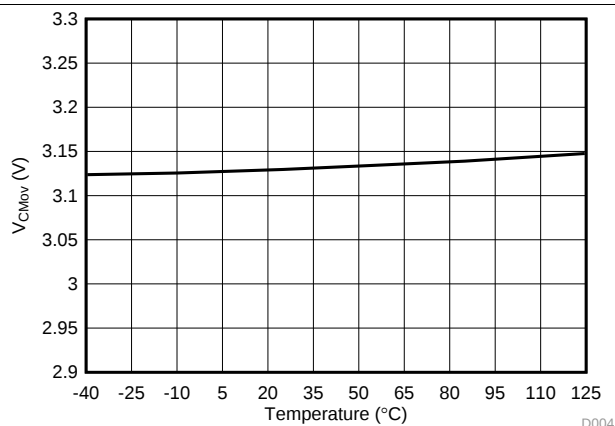


Figure 6. Common-Mode Overvoltage Detection Level vs Temperature

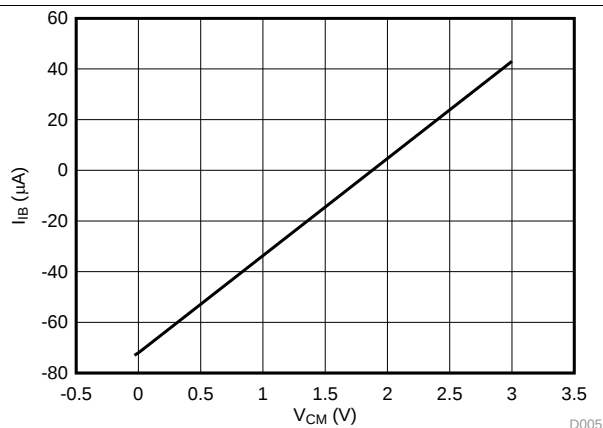


Figure 7. Input Bias Current vs Common-Mode Input Voltage

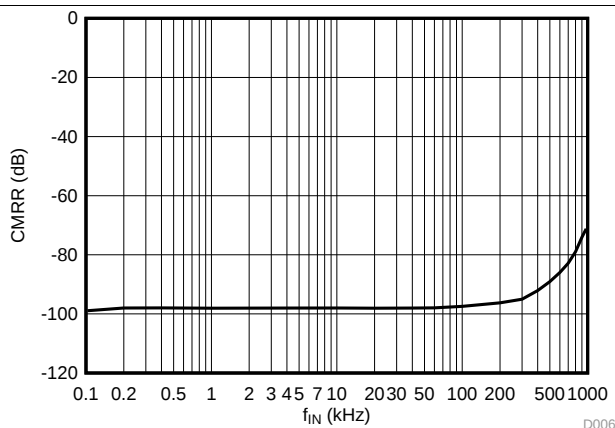


Figure 8. Common-Mode Rejection Ratio vs Input Signal Frequency

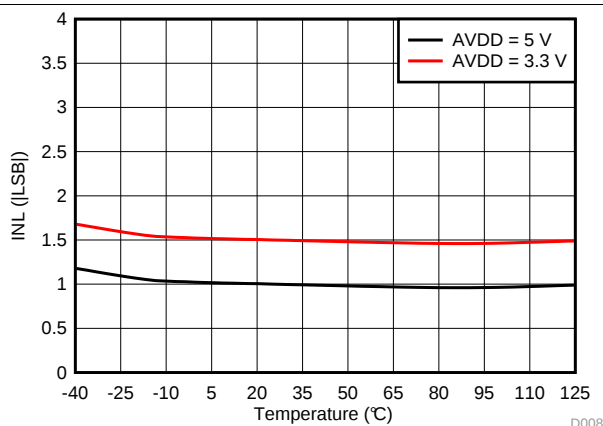


Figure 9. Integral Nonlinearity vs Temperature

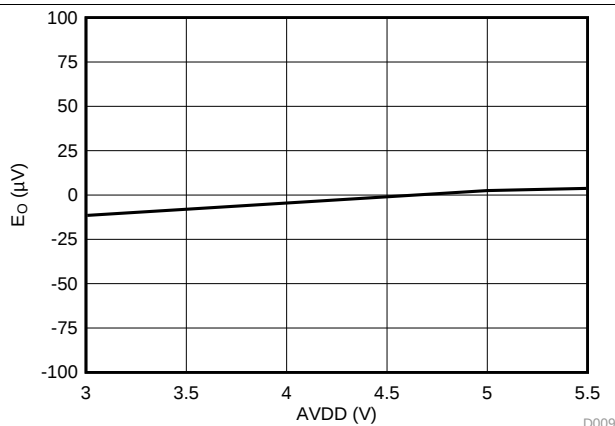


Figure 10. Offset Error vs High-Side Supply Voltage

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $AVDD = 5\text{ V}$, $DVDD = 3.3\text{ V}$, $AINP = -50\text{ mV to } 50\text{ mV}$, $AINN = AGND$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256 (unless otherwise noted)

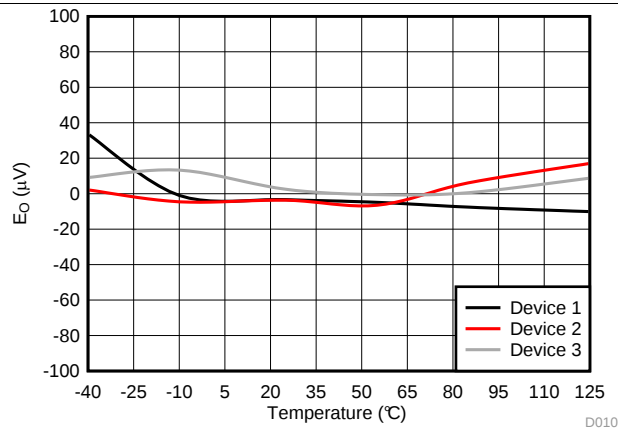


Figure 11. Offset Error vs Temperature

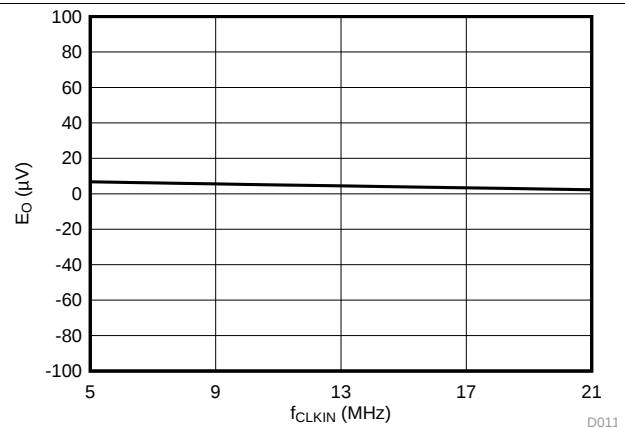


Figure 12. Offset Error vs Clock Frequency

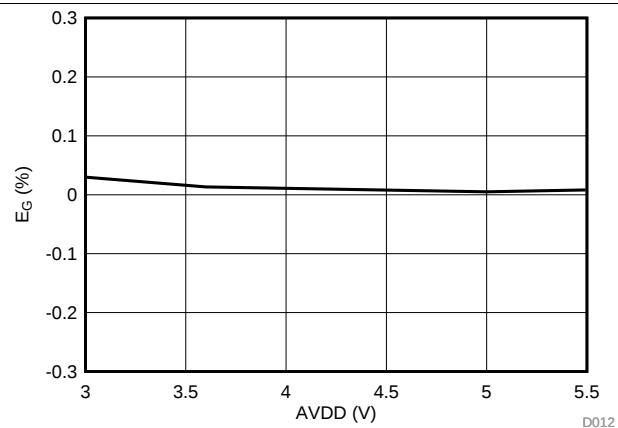


Figure 13. Gain Error vs High-Side Supply Voltage

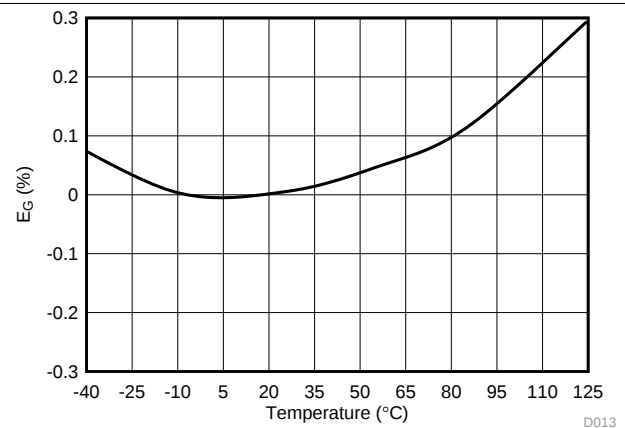


Figure 14. Gain Error vs Temperature

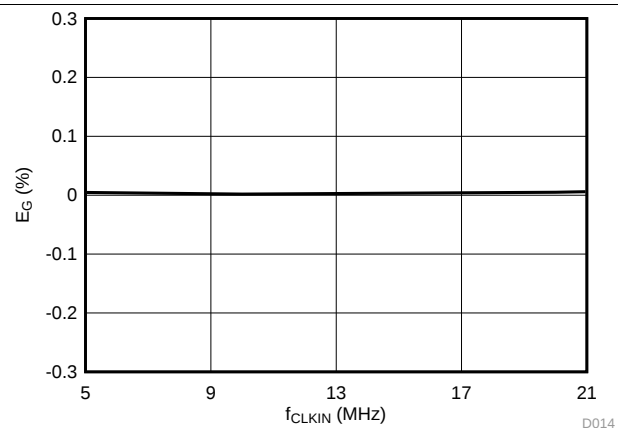


Figure 15. Gain Error vs Clock Frequency

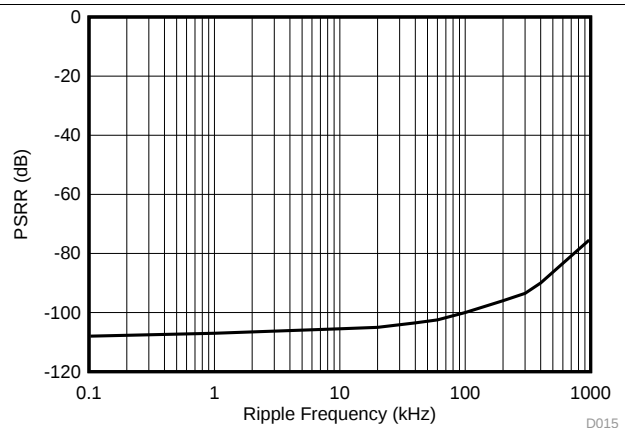


Figure 16. Power-Supply Rejection Ratio vs Ripple Frequency

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $AVDD = 5\text{ V}$, $DVDD = 3.3\text{ V}$, $AINP = -50\text{ mV to }50\text{ mV}$, $AINN = \text{AGND}$, $f_{\text{CLKIN}} = 20\text{ MHz}$, and sinc³ filter with OSR = 256 (unless otherwise noted)

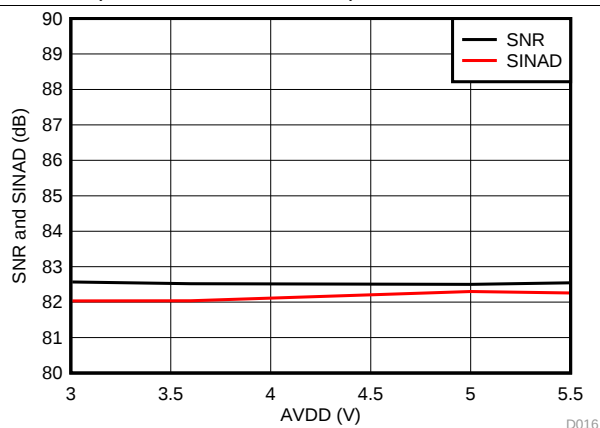


Figure 17. Signal-to-Noise Ratio and Signal-to-Noise + Distortion vs High-Side Supply Voltage

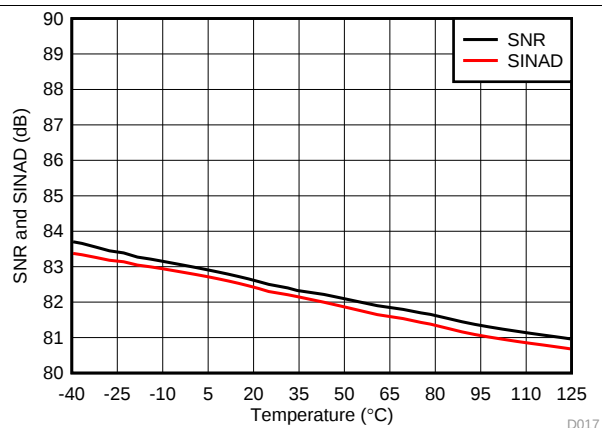


Figure 18. Signal-to-Noise Ratio and Signal-to-Noise + Distortion vs Temperature

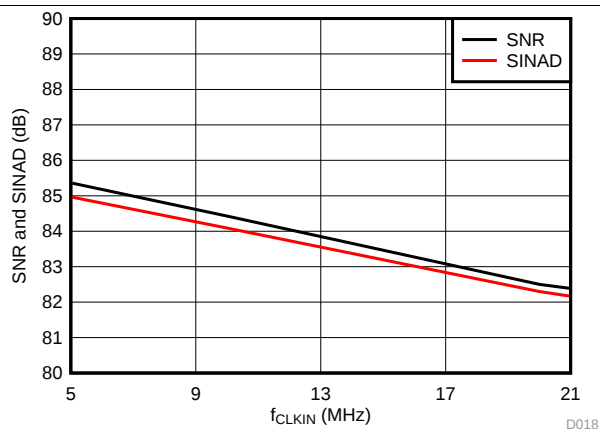


Figure 19. Signal-to-Noise Ratio and Signal-to-Noise + Distortion vs Clock Frequency

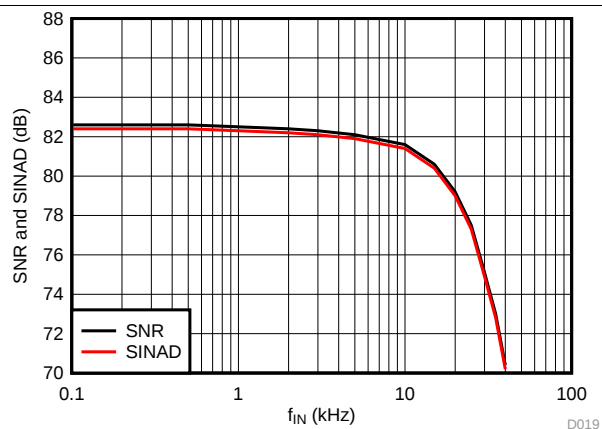


Figure 20. Signal-to-Noise Ratio and Signal-to-Noise + Distortion vs Input Signal Frequency

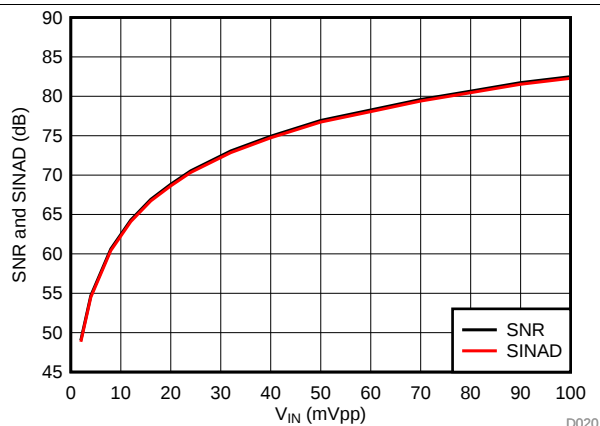


Figure 21. Signal-to-Noise Ratio and Signal-to-Noise + Distortion vs Input Signal Amplitude

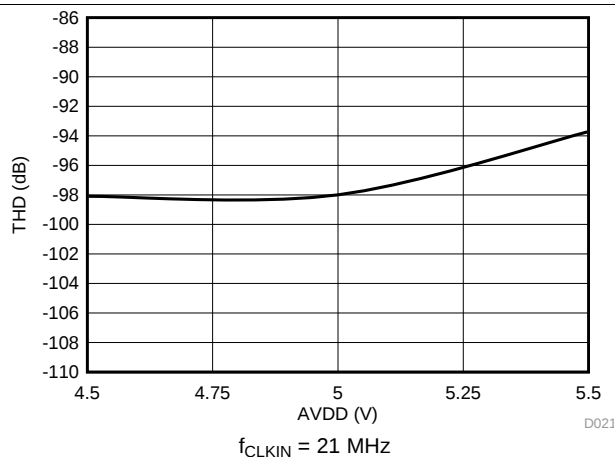


Figure 22. Total Harmonic Distortion vs High-Side Supply Voltage

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -50\text{ mV}$ to 50 mV , $A_{INN} = \text{AGND}$, $f_{\text{CLKIN}} = 20\text{ MHz}$, and sinc^3 filter with $\text{OSR} = 256$ (unless otherwise noted)

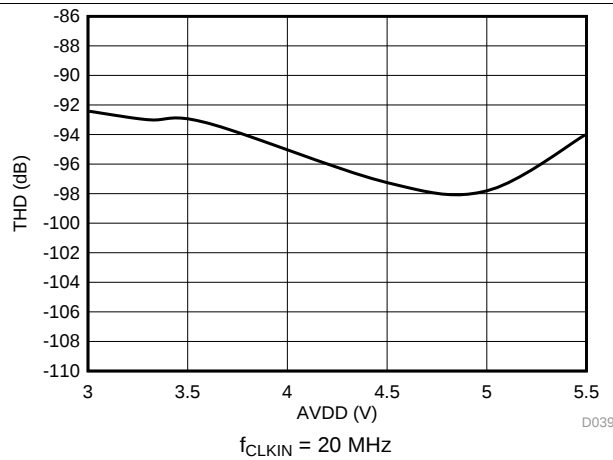


Figure 23. Total Harmonic Distortion vs High-Side Supply Voltage

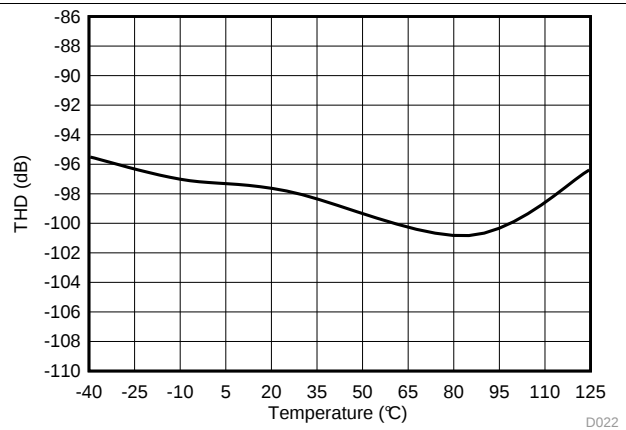


Figure 24. Total Harmonic Distortion vs Temperature

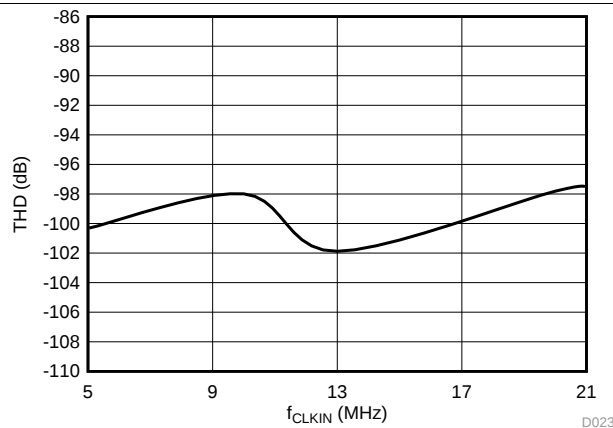


Figure 25. Total Harmonic Distortion vs Clock Frequency

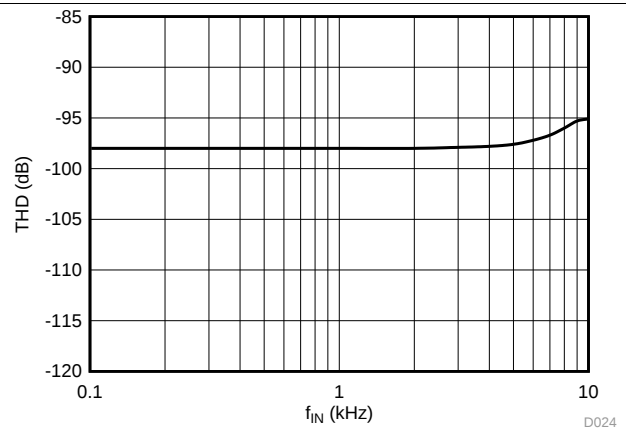


Figure 26. Total Harmonic Distortion vs Input Signal Frequency

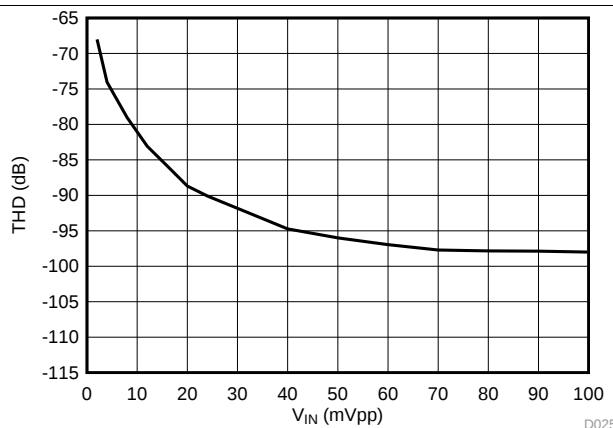


Figure 27. Total Harmonic Distortion vs Input Signal Amplitude

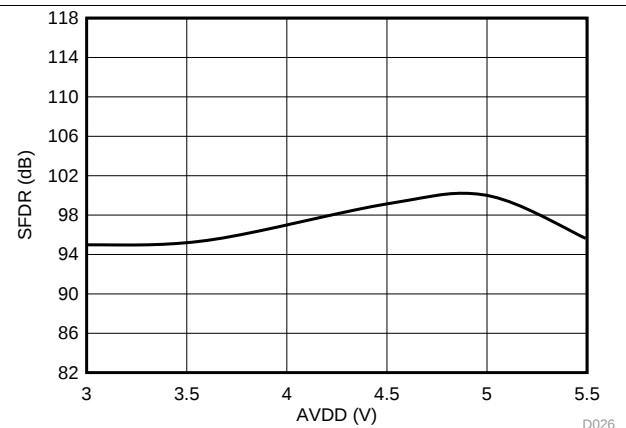


Figure 28. Spurious-Free Dynamic Range vs High-Side Supply Voltage

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $AV_{DD} = 5\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -50\text{ mV}$ to 50 mV , $A_{INN} = \text{AGND}$, $f_{\text{CLKIN}} = 20\text{ MHz}$, and sinc³ filter with OSR = 256 (unless otherwise noted)

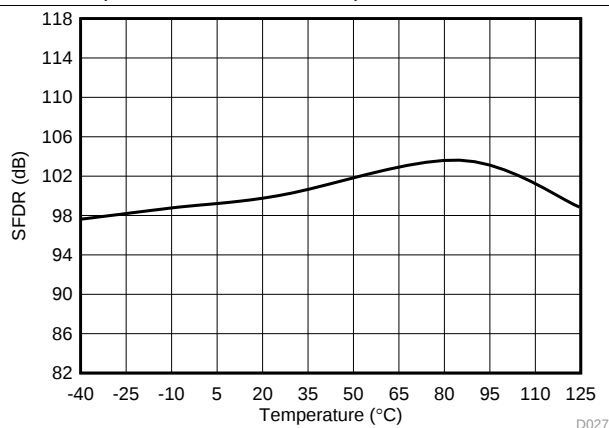


Figure 29. Spurious-Free Dynamic Range vs Temperature

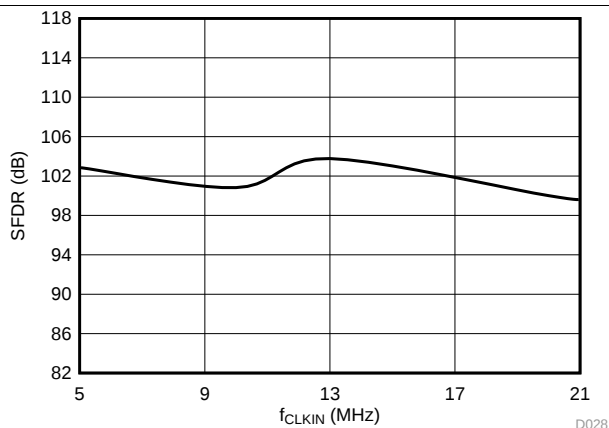


Figure 30. Spurious-Free Dynamic Range vs Clock Frequency

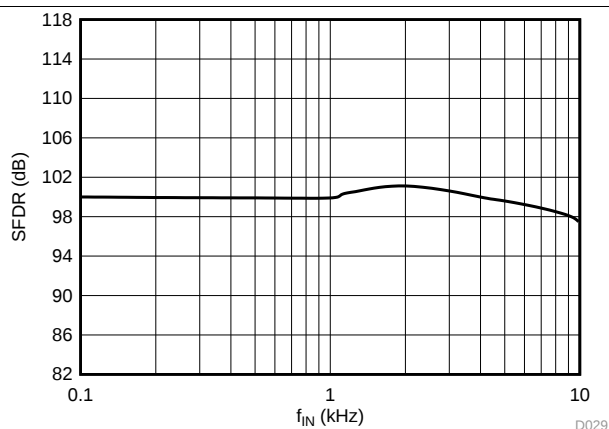


Figure 31. Spurious-Free Dynamic Range vs Input Signal Frequency

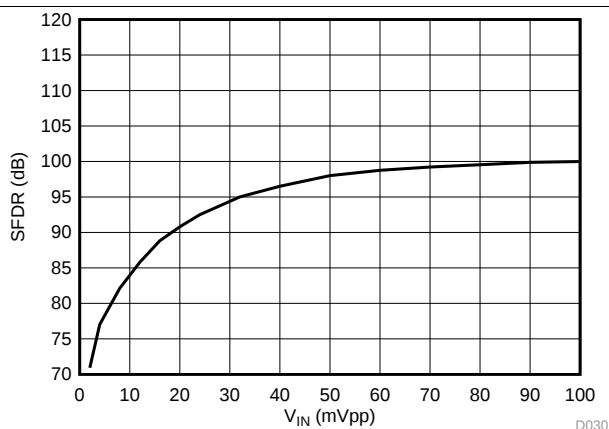


Figure 32. Spurious-Free Dynamic Range vs Input Signal Amplitude

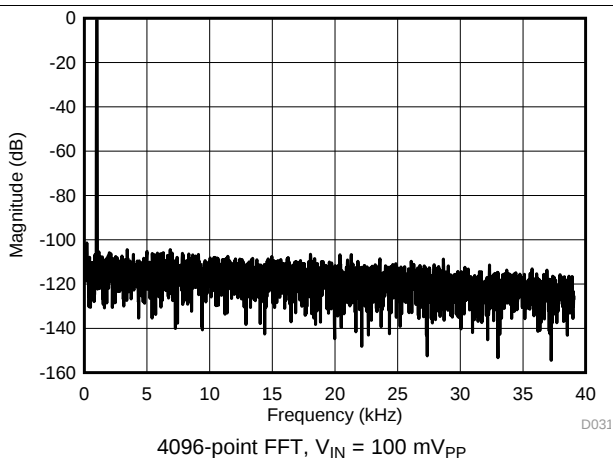


Figure 33. Frequency Spectrum With 1-kHz Input Signal

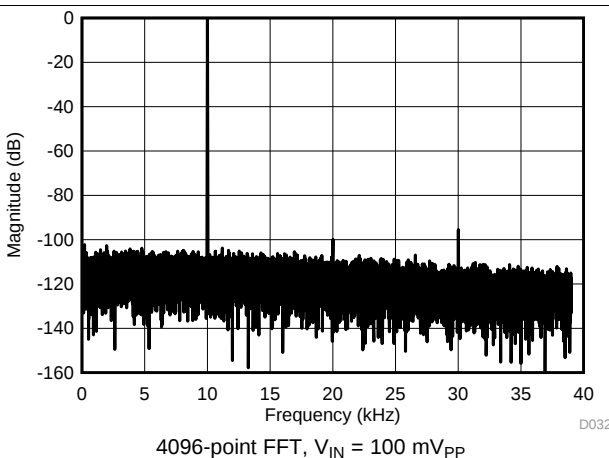


Figure 34. Frequency Spectrum With 10-kHz Input Signal

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $AVDD = 5\text{ V}$, $DVDD = 3.3\text{ V}$, $AINP = -50\text{ mV to }50\text{ mV}$, $AINN = AGND$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256 (unless otherwise noted)

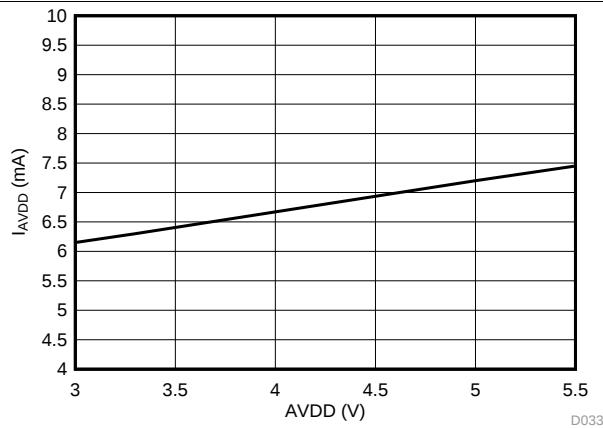


Figure 35. High-Side Supply Current vs High-Side Supply Voltage

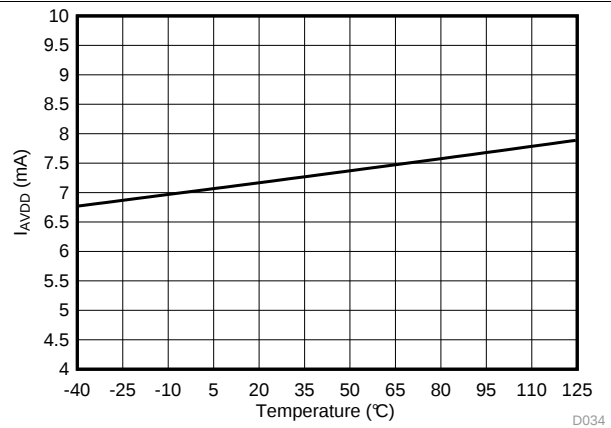


Figure 36. High-Side Supply Current vs Temperature

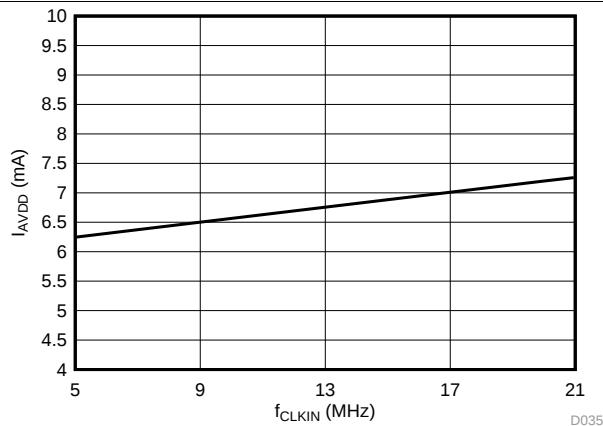


Figure 37. High-Side Supply Current vs Clock Frequency

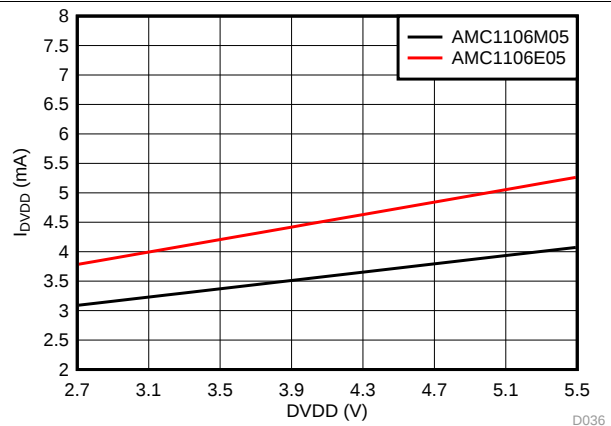


Figure 38. Controller-Side Supply Current vs Controller-Side Supply Voltage

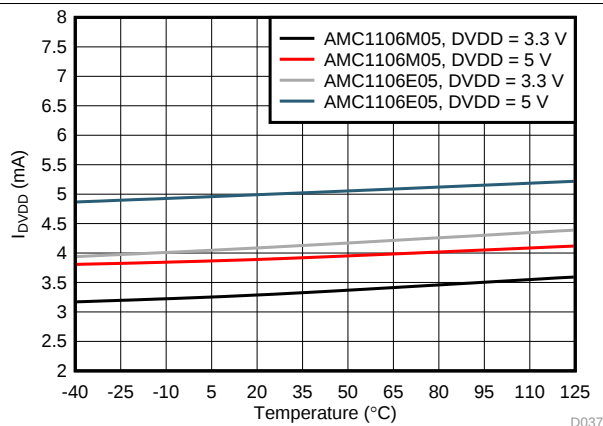


Figure 39. Controller-Side Supply Current vs Temperature

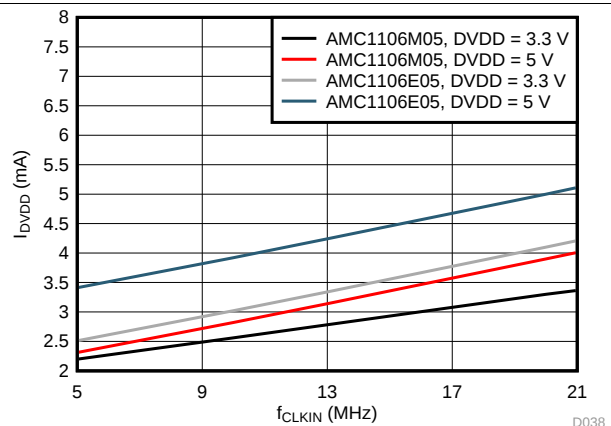


Figure 40. Controller-Side Supply Current vs Clock Frequency

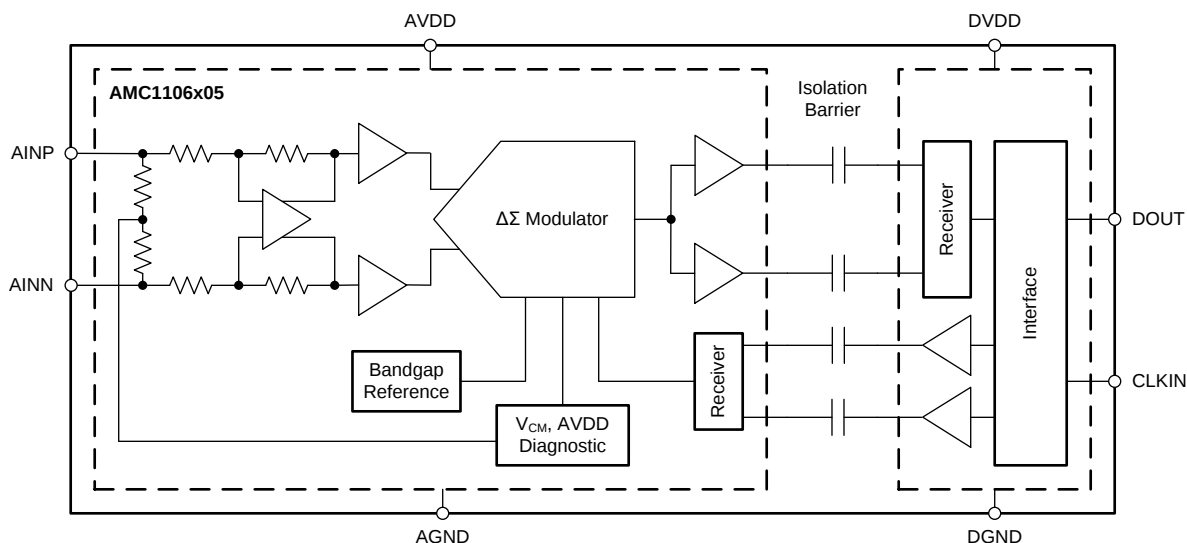
8 Detailed Description

8.1 Overview

The analog input stage of the AMC1106 is a fully differential amplifier that feeds the second-order, delta-sigma ($\Delta\Sigma$) modulator that digitizes the input signal into a 1-bit output stream. The isolated data output DOUT of the converter provides a stream of digital ones and zeros that is synchronous to the externally-provided clock source at the CLKIN pin with a frequency as specified in the [Switching Characteristics](#) table. The time average of this serial bitstream output is proportional to the analog input voltage.

The [Functional Block Diagram](#) section shows a detailed block diagram of the AMC1106. The analog input range is tailored to directly accommodate a voltage drop across a shunt resistor used for current sensing. The silicon-dioxide (SiO_2) based capacitive isolation barrier supports a high level of magnetic field immunity as described in the [ISO72x Digital Isolator Magnetic-Field Immunity](#) application report, available for download at www.ti.com. The external clock input simplifies the synchronization of multiple current-sensing channels on the system level. The extended frequency range of up to 21 MHz supports higher performance levels compared to the other solutions available on the market.

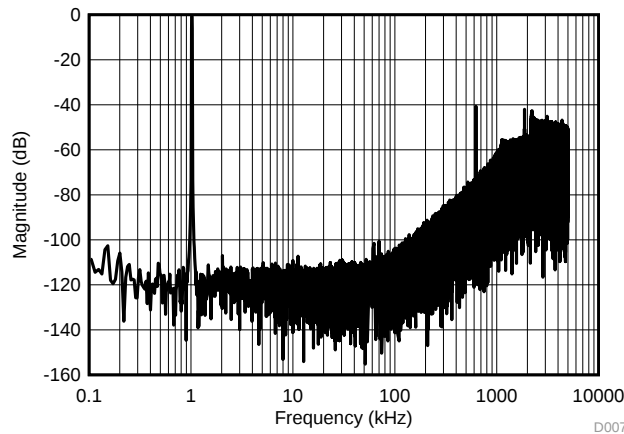
8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Analog Input

The AMC1106 incorporates front-end circuitry that contains a differential amplifier and sampling stage, followed by a $\Delta\Sigma$ modulator. The gain of the differential amplifier is set by internal precision resistors to a factor of 20 with a differential input resistance of 4.9 k Ω . For reduced offset and offset drift, the differential amplifier is chopper-stabilized with the switching frequency set at $f_{CLKIN} / 32$. Figure 41 shows that the switching frequency generates a spur. The impact of this spur on the overall system-level performance depends on the digital filter settings.



sinc^3 filter, $\text{OSR} = 2$, $f_{CLKIN} = 20 \text{ MHz}$, $f_{IN} = 1 \text{ kHz}$

Figure 41. Quantization Noise Shaping

There are two restrictions on the analog input signals (AINP and AINN). First, if the input voltage exceeds the range $\text{AGND} - 6 \text{ V}$ to $\text{AVDD} + 0.5 \text{ V}$, the input current must be limited to 10 mA because the device input electrostatic discharge (ESD) diodes turn on. In addition, the linearity and noise performance of the device are ensured only when the differential analog input voltage remains within the specified linear full-scale range (FSR) and within the specified input common-mode voltage range (V_{CM}).

Feature Description (continued)

8.3.2 Modulator

The modulator implemented in the AMC1106 (such as the one conceptualized in [Figure 42](#)) is a second-order, switched-capacitor, feed-forward $\Delta\Sigma$ modulator. The analog input voltage V_{IN} and the output V_5 of the 1-bit digital-to-analog converter (DAC) are subtracted, providing an analog voltage V_1 at the input of the first integrator stage. The output of the first integrator feeds the input of the second integrator stage, resulting in output voltage V_3 that is subtracted from the input signal V_{IN} and the output of the first integrator V_2 . Depending on the polarity of the resulting voltage V_4 , the output of the comparator is changed. In this case, the 1-bit DAC responds on the next clock pulse by changing its analog output voltage V_5 , causing the integrators to progress in the opposite direction and forcing the value of the integrator output to track the average value of the input.

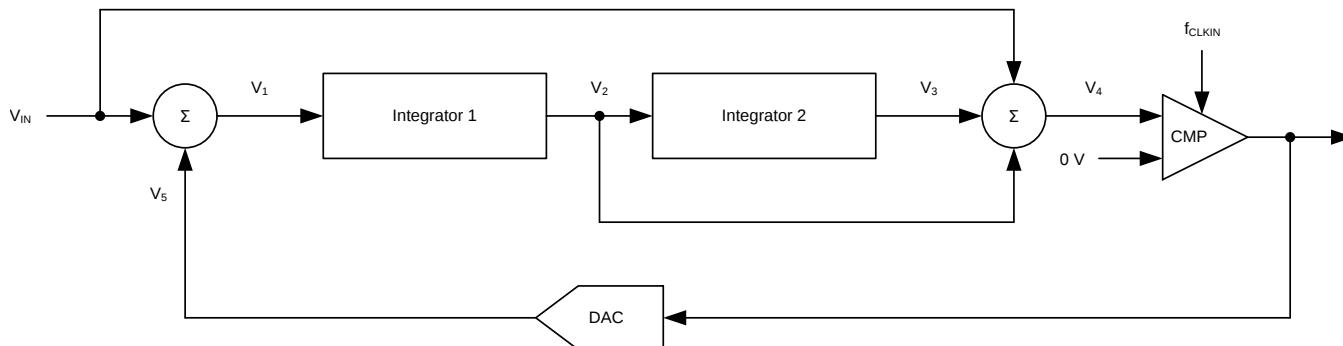


Figure 42. Block Diagram of a Second-Order Modulator

The modulator shifts the quantization noise to high frequencies; see [Figure 41](#). Therefore, use a low-pass digital filter at the output of the device to increase the overall performance. This filter is also used to convert from the 1-bit data stream at a high sampling rate into a higher-bit data word at a lower rate (decimation). TI's microcontroller family [MSP430F67x](#) offers a path to directly access the integrated sinc-filters of the SD24_B ADCs for a simple system-level solution for multichannel, isolated current sensing. Also, the microcontroller families [TMS320F2807x](#) and [TMS320F2837x](#) offer a suitable programmable, hardwired filter structure termed a *sigma-delta filter module* (SDFM) optimized for usage with the AMC1106. An additional option is to use a suitable application-specific device, such as the [AMC1210](#) (a four-channel digital sinc-filter). Alternatively, a field-programmable gate array (FPGA) can be used to implement the filter.

Feature Description (continued)

8.3.3 Isolation Channel Signal Transmission

The AMC1106 uses an on-off keying (OOK) modulation scheme to transmit the modulator output bitstream across the capacitive SiO₂-based isolation barrier. The transmitter modulates the bitstream at TX IN in [Figure 43](#) with an internally-generated, 480-MHz carrier across the isolation barrier to represent a digital *one* and sends a *no signal* to represent the digital *zero*. The receiver demodulates the signal after advanced signal conditioning and produces the output. The symmetrical design of each isolation channel improves the CMTI performance and reduces the radiated emissions caused by the high-frequency carrier. [Figure 43](#) shows a block diagram of an isolation channel integrated in the AMC1106.

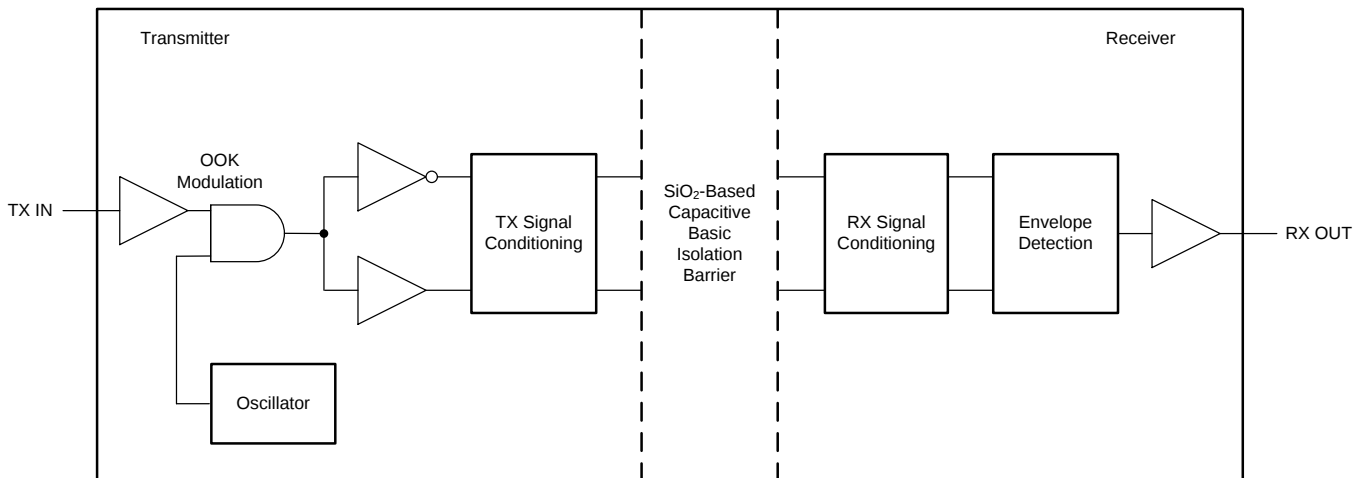


Figure 43. Block Diagram of an Isolation Channel

[Figure 44](#) shows the concept of the on-off keying scheme.

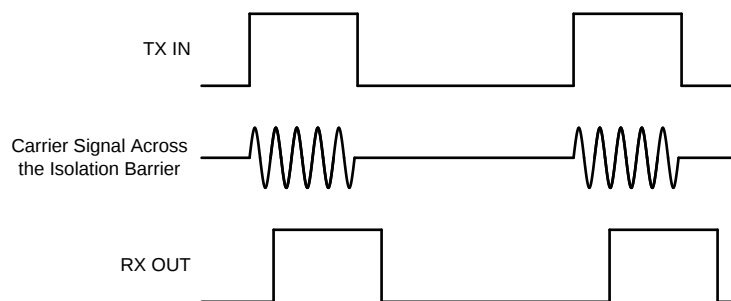


Figure 44. OOK-Based Modulation Scheme

Feature Description (continued)

8.3.4 Digital Output

A differential input signal of 0 V ideally produces a stream of ones and zeros that are high 50% of the time. A differential input of 50 mV produces a stream of ones and zeros that are high 89.06% of the time. With 16 bits of resolution on the decimation filter, that percentage ideally corresponds to code 58368. A differential input of –50 mV produces a stream of ones and zeros that are high 10.94% of the time and ideally results in code 7168 with a 16-bit resolution decimation filter. This –50-mV to 50-mV input voltage range is also the specified linear range FSR of the AMC1106 with performance as specified in this document. If the input voltage value exceeds this range, the output of the modulator shows nonlinear behavior where the quantization noise increases. The output of the modulator clips with a stream of only zeros with an input less than or equal to –64 mV or with a stream of only ones with an input greater than or equal to 64 mV. In this case, however, the AMC1106 generates a single 1 (if the input is at negative full-scale) or 0 every 128 clock cycles to indicate proper device function (see the [Fail-Safe Output](#) section for more details). [Figure 45](#) shows the input voltage versus the modulator output signal.

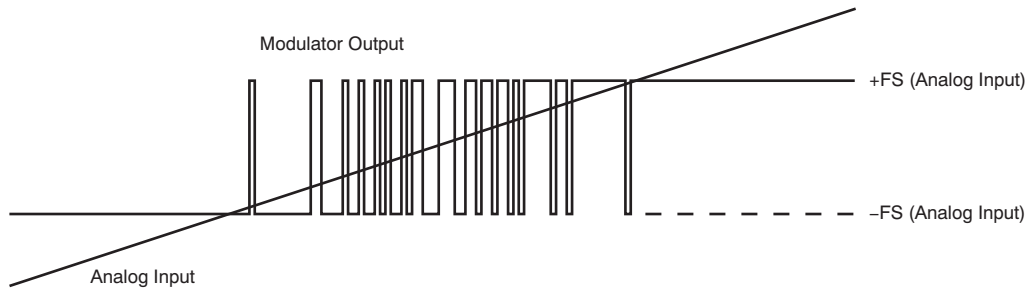


Figure 45. Analog Input versus AMC1106 Modulator Output

[Equation 1](#) calculates the density of ones in the output bitstream for any input voltage value (with the exception of a full-scale input signal, as described in the [Output Behavior in Case of a Full-Scale Input](#) section):

$$\frac{V_{IN} + V_{Clipping}}{2 \times V_{Clipping}} \quad (1)$$

The AMC1106 system clock is provided externally at the CLKIN pin. For more details, see the [Switching Characteristics](#) table and the [Manchester Coding Feature](#) section.

8.3.5 Manchester Coding Feature

The AMC1106E05 offers the IEEE 802.3-compliant Manchester coding feature that generates at least one transition per bit to support clock signal recovery from the bitstream. A Manchester coded bitstream is free of dc components and supports single-wire data and clock transfer without having to consider the setup and hold time requirements of the receiving device. The Manchester coding combines the clock and data information using exclusive or (XOR) logical operation. [Figure 46](#) shows the resulting bitstream. The duty cycle of the Manchester encoded bitstream depends on the duty cycle of the input clock CLKIN.

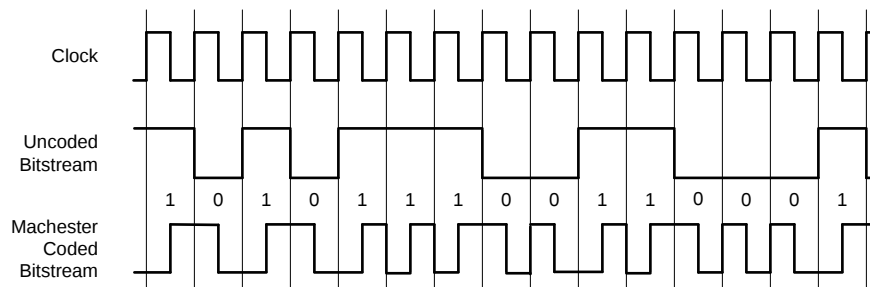


Figure 46. Manchester Coded Output of the AMC1106E05

8.4 Device Functional Modes

8.4.1 Fail-Safe Output

In the case of a missing AVDD high-side supply voltage, the output of the $\Delta\Sigma$ modulator is not defined and can cause a system malfunction. In systems with high safety requirements, this behavior is not acceptable. Therefore, as shown in Figure 47, the AMC1106 implements a fail-safe output function that ensures that the DOUT output of the device offers a steady-state bitstream of logic 0's in case of a missing AVDD.

Similarly, as also shown in Figure 47, if the common-mode voltage of the input reaches or exceeds the specified common-mode overvoltage detection level V_{CMov} as defined in the [Electrical Characteristics](#) table, the AMC1106 generates a steady-state bitstream of logic 1's at the DOUT output.

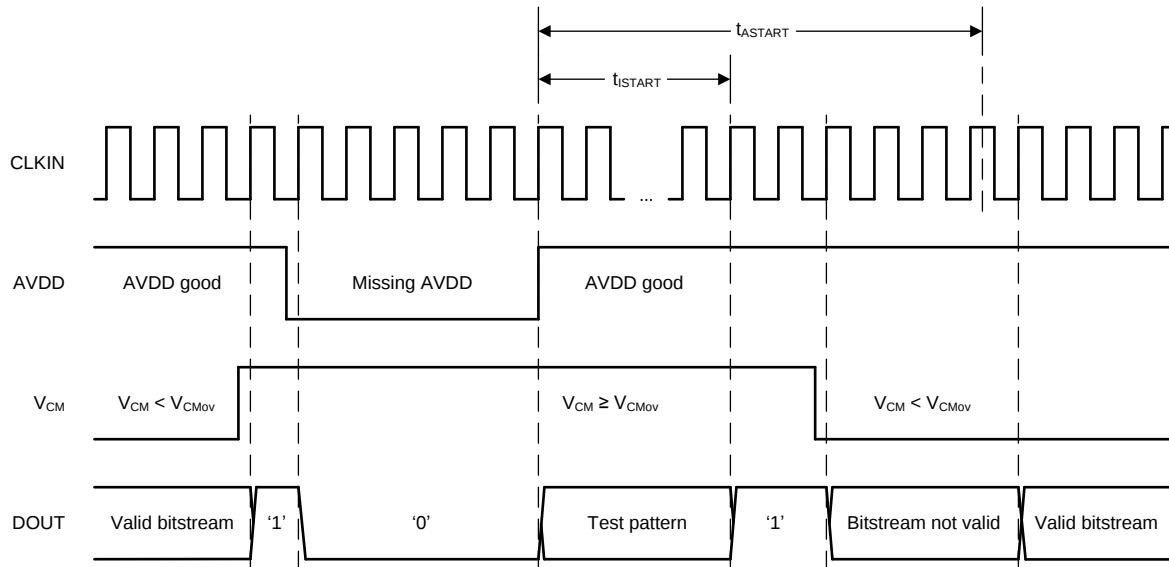


Figure 47. Fail-Safe Output of the AMC1106

8.4.2 Output Behavior in Case of a Full-Scale Input

If a full-scale input signal is applied to the AMC1106 (that is, $|V_{IN}| \geq |V_{Clipping}|$), Figure 48 shows that the device generates a single one or zero every 128 bits at DOUT, depending on the actual polarity of the signal being sensed. In this way, differentiating between a missing AVDD and a full-scale input signal is possible on the system level.

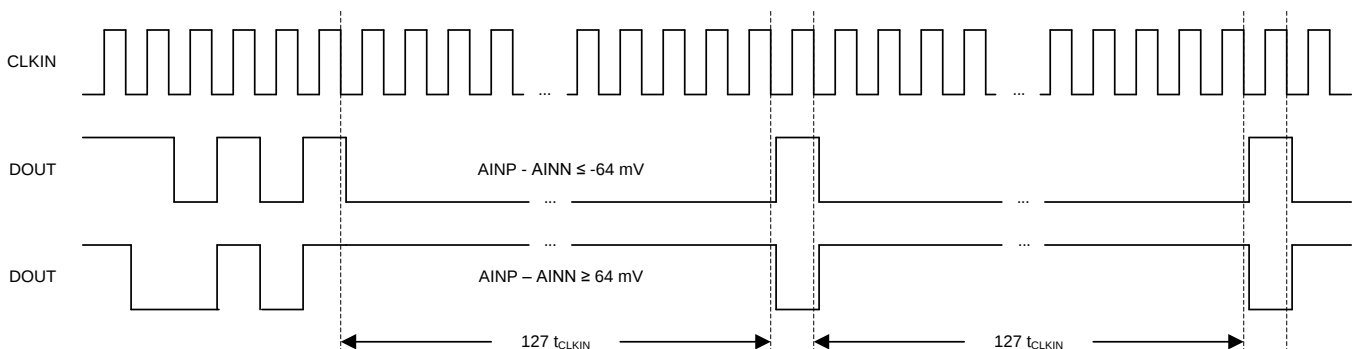


Figure 48. Overrange Output of the AMC1106

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 Digital Filter Usage

The modulator generates a bit stream that is processed by a digital filter to obtain a digital word similar to a conversion result of a conventional analog-to-digital converter (ADC). A very simple filter, shown in [Equation 2](#), built with minimal effort and hardware, is a sinc³-type filter:

$$H(z) = \left(\frac{1 - z^{-OSR}}{1 - z^{-1}} \right)^3 \quad (2)$$

This filter provides the best output performance at the lowest hardware size (count of digital gates) for a second-order modulator. All the characterization in this document is also done with a sinc³ filter with an oversampling ratio (OSR) of 256 and an output word width of 16 bits.

An example code for implementing a sinc³ filter in an FPGA is discussed in application note [Combining ADS1202 with FPGA Digital Filter for Current Measurement in Motor Control Applications](#), available for download at www.ti.com.

9.2 Typical Application

$\Delta\Sigma$ ADCs are widely used for current measurement in electricity meters because of the high ac accuracy obtained over a wide dynamic range that is achieved by averaging in the digital filter. As a result of their inherent isolation, current transformers (CT) were commonly used as current sensors in 3-phase electricity meters in the past. A strong magnetic field can saturate a CT and stop proper energy measurement. Shunt resistors are immune to magnetic fields and can be used to design temper-free electricity meters. The input structure of the AMC1106 is optimized for use with low-impedance shunt resistors to minimize the power dissipation of the circuit. The transformerless galvanic isolation of the bitstream as implemented in the AMC1106 is tailored for shunt-based current sensing in modern 3-phase electricity meter designs.

Figure 49 shows a simplified schematic of the AMC1106 in a shunt-based, 3-phase electricity meter application.

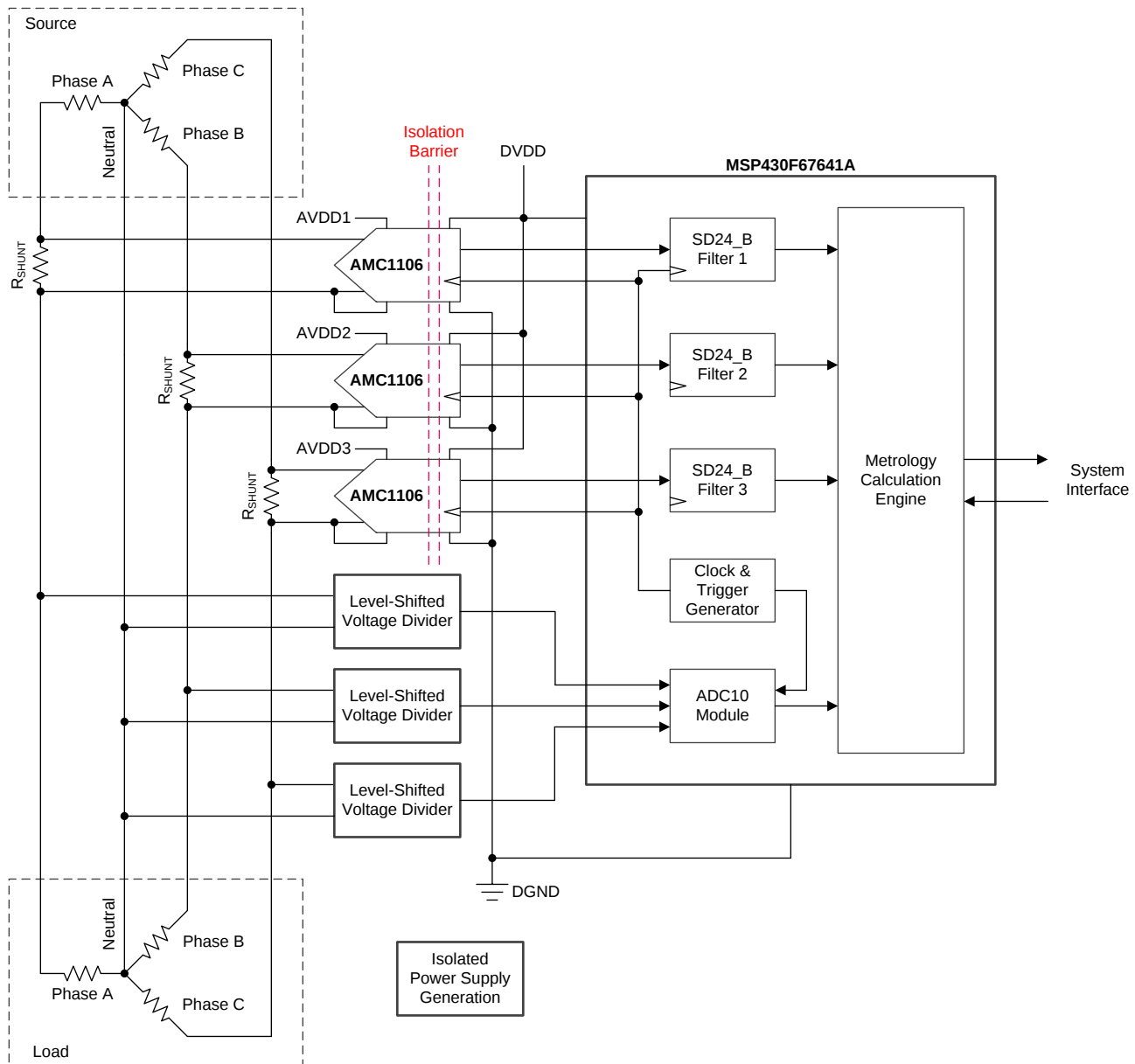


Figure 49. The AMC1106 in a 3-Phase Electricity Meter Application

Typical Application (continued)

9.2.1 Design Requirements

Table 1 lists the parameters for the this typical application.

Table 1. Design Requirements

PARAMETER	VALUE
AVDD1, AVDD2, and AVDD3 high-side supply voltages	3.3 V or 5 V
DVDD low-side supply voltage	3.3 V or 5 V
Voltage drop across the shunt for a linear response	±50 mV (maximum)
Accuracy	Class 0.5 or better

9.2.2 Detailed Design Procedure

The high-side power supply (AVDD) for the AMC1106 is externally derived from either a capacitive-drop or a coreless transformer power-supply circuit. Further details are provided in the [Power Supply Recommendations](#) section.

The floating ground reference (AGND) is derived from one of the ends of the shunt resistor that is connected to the analog inputs of the AMC1106. If a four-pin shunt is used, the inputs of the device are connected to the inner leads and AGND is connected to one of the outer shunt leads.

Use Ohm's Law to calculate the voltage drop across the shunt resistor (V_{SHUNT}) for the desired measured current: $V_{SHUNT} = I \times R_{SHUNT}$.

Consider the following two restrictions to choose the proper value of the shunt resistor R_{SHUNT} :

- The voltage drop caused by the nominal current range must not exceed the recommended differential input voltage range: $V_{SHUNT} \leq \pm 50 \text{ mV}$
- The voltage drop caused by the maximum allowed overcurrent must not exceed the input voltage that causes a clipping output: $|V_{SHUNT}| \leq |V_{Clipping}|$

Use an RC filter in front of the AMC1106 to improve the overall signal-to-noise performance of the system and improve the immunity of the circuit to high-frequency electromagnetic fields.

For the AMC1106 output bitstream averaging, a poly-phase device version from TI's [MSP430F67x](#) family of low-power microcontrollers (MCUs) is recommended. This family offers the sigma-delta module (SD24_B) that allows for bypassing the internal modulator and directly accessing the digital filter. The integrated trigger and clock generator support synchronization of all three AMC1106 devices and the internal 10-bit SAR ADC that is used to deliver the voltage information of all phases.

Figure 50 shows a voltage divider circuit with a common-mode set to 1/3 of the supply voltage that is used to adjust the mains voltage signal to the input voltage range of the SAR ADC used in the MSP430F67641A.

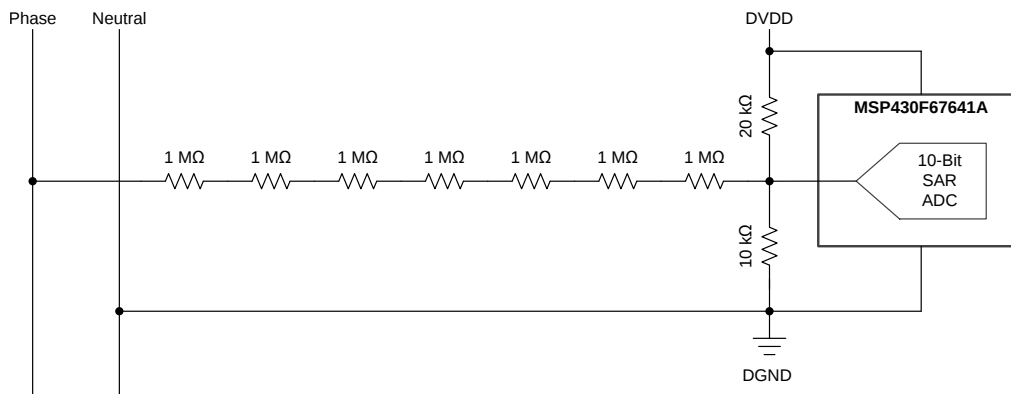


Figure 50. Level-Shifted Voltage Divider

For further design recommendations and system level considerations, see the [Multi-Phase Power Quality Measurement With Isolated Shunt Sensors](#) or the [Magnetically Immune Transformerless Power Supply for Isolated Shunt Current Measurement](#) reference designs offered by TI.

9.2.3 Application Curve

In electricity metering applications, the initial calibration of the offset, gain, and phase errors is absolutely necessary to correctly sense the current and voltage signals, and calculate the power with the required system level accuracy as per regional regulations. After system calibration, an electricity meter circuit based on the shunt resistors, the AMC1106, and the MSP430F67x support error levels below $\pm 0.2\%$, as shown in [Figure 51](#) and the documentation of the reference designs listed previously.

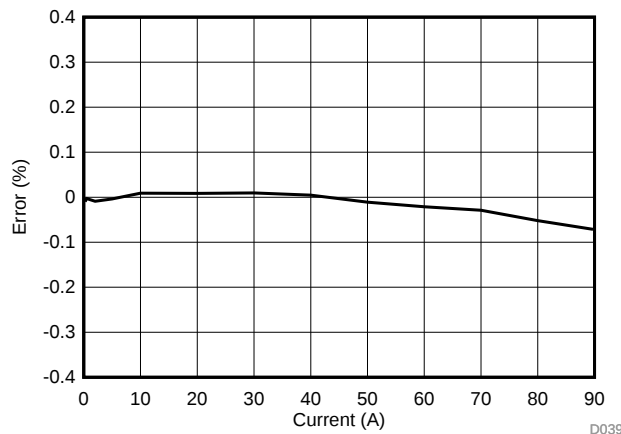


Figure 51. Active Energy Error

9.2.4 Do's and Don'ts

Do not leave the inputs of the AMC1106 unconnected (floating) when the device is powered up. If both modulator inputs are left floating, the input bias current drives these inputs to the output common-mode voltage level of the differential amplifier of approximately 1.9 V. If that voltage is above the specified input common-mode range, the gain of the differential amplifier diminishes and the modulator outputs a bitstream resembling a zero differential input voltage.

10 Power Supply Recommendations

For lowest system-level cost, the high-side power supply (AVDD) for the AMC1106 is derived from an external capacitive-drop power supply. The [Magnetically Immune Transformerless Power Supply for Isolated Shunt Current Measurement](#) reference design and [Figure 52](#) shows a proven solution based on a 6.2-V diode and the [TLV70450](#) 5-V low dropout (LDO) regulator. A low equivalent series resistance (ESR) decoupling capacitor of 0.1 μF is recommended for filtering this power-supply path. Place this capacitor (C5 in [Figure 52](#)) as close as possible to the AVDD pin of the AMC1106 for best performance.

The floating ground reference (AGND) is derived from the end of the shunt resistor that is also connected to the negative input (AINN) of the device. If a four-pin shunt is used, the device inputs are connected to the inner leads and AGND is connected to one of the outer leads of the shunt.

For decoupling of the digital power supply on the controller side, TI recommends using a 0.1- μF capacitor (C6 in [Figure 52](#)) assembled as close to the DVDD pin of the AMC1106 as possible, followed by an additional capacitor in the range of 1 μF to 10 μF .

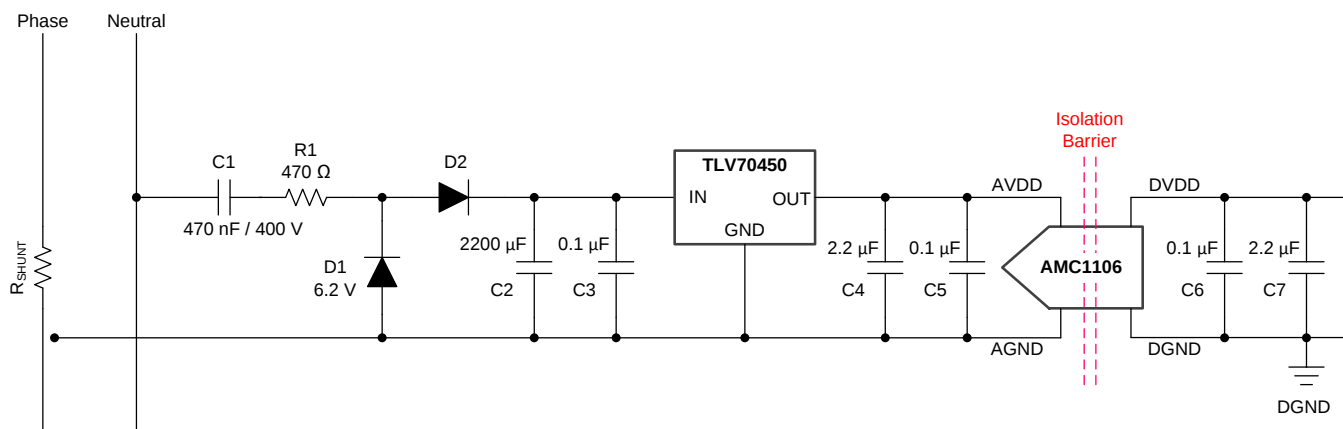


Figure 52. Capacitive-Drop Solution for the AMC1106 AVDD Supply

11 Layout

11.1 Layout Guidelines

Figure 53 shows a layout recommendation example based on an on-board, 4-wire shunt resistor that details the critical placement of the decoupling capacitors (as close as possible to the AMC1106 supply pins) and the placement of the other components required by the device. For best performance, place the shunt resistor close to the AINP and AINN inputs of the AMC1106 and keep the layout of both connections symmetrical.

11.2 Layout Example

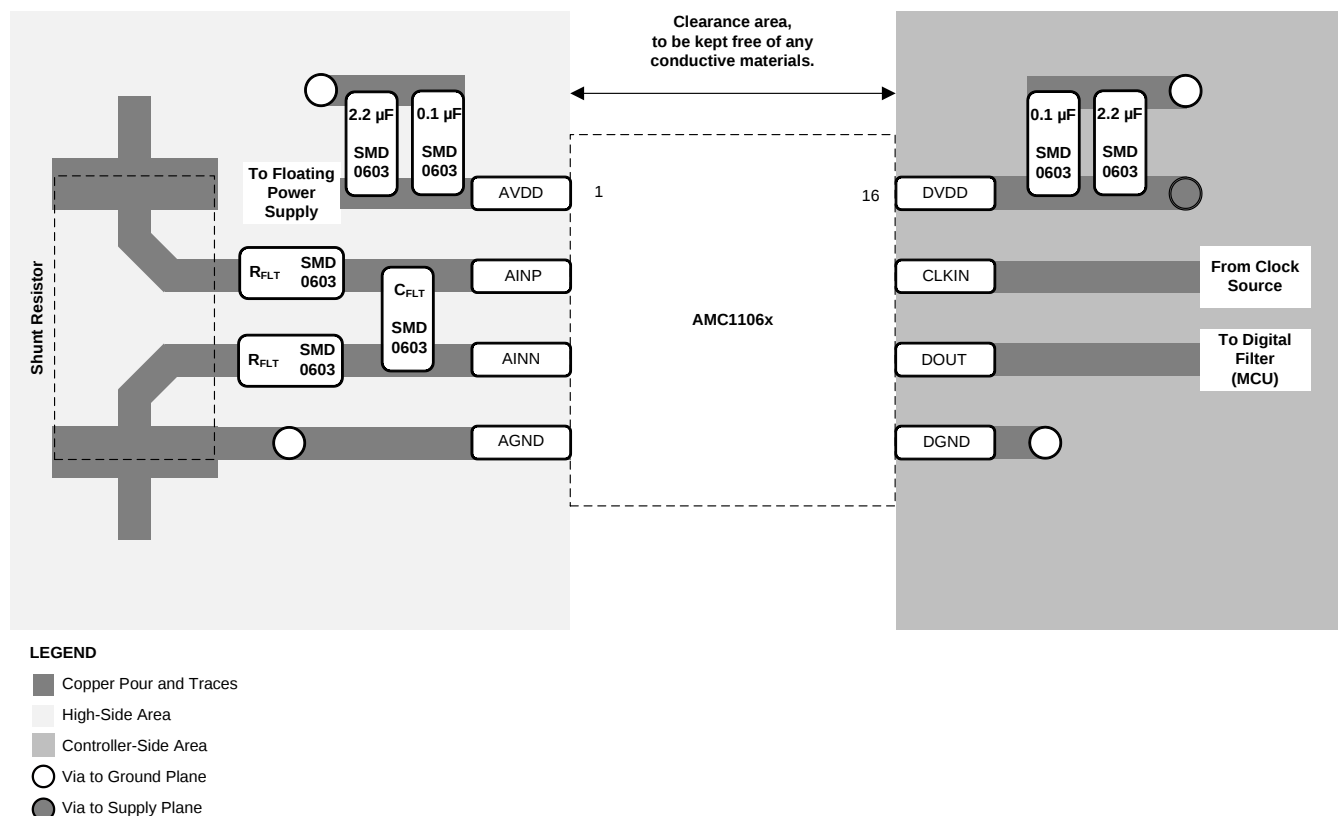


Figure 53. Recommended Layout of the AMC1106

12 デバイスおよびドキュメントのサポート

12.1 デバイス・サポート

12.1.1 デバイスの項目表記

12.1.1.1 絶縁の用語集

『[絶縁の用語集](#)』を参照してください。

12.2 ドキュメントのサポート

12.2.1 関連資料

関連資料については、以下を参照してください。

- 『[AMC1210 2次デルタ-シグマ変調器用のクワッド・デジタル・フィルタ](#)』
- 『[MSP430F67x ポリフェーズ計量SoC](#)』
- 『[TMS320F2807x Piccolo™ マイクロコントローラ](#)』
- 『[TMS320F2837xD デュアルコアDelfino™ マイクロコントローラ](#)』
- 『[TLV704 24V入力電圧、150mA、超低 \$I_Q\$ 低ドロップアウト・レギュレータ](#)』
- 『[ISO72x デジタル・アイソレータの磁場耐性](#)』
- 『[ADS1202とFPGA デジタル・フィルタとの組み合わせによるモータ制御アプリケーションでの電流測定](#)』
- 『[多相電源品質測定、絶縁シャント・センサ採用](#)』
- 『[磁気耐性トランスレス、絶縁シャント電流測定用電源](#)』

12.3 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびご注文へのクイック・アクセスが含まれます。

表 2. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
AMC1106E05	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
AMC1106M05	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

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12.5 コミュニティ・リソース

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12.8 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
AMC1106E05DWV	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106E05DWV.A	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106E05DWV.B	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106E05DWVR	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106E05DWVR.A	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106E05DWVR.B	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106E05
AMC1106M05DWV	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05
AMC1106M05DWV.A	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05
AMC1106M05DWV.B	Active	Production	SOIC (DWV) 8	64 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05
AMC1106M05DWVR	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05
AMC1106M05DWVR.A	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05
AMC1106M05DWVR.B	Active	Production	SOIC (DWV) 8	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	1106M05

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AMC1106E05DWVR	SOIC	DWV	8	1000	330.0	16.4	12.05	6.15	3.3	16.0	16.0	Q1
AMC1106M05DWVR	SOIC	DWV	8	1000	330.0	16.4	12.05	6.15	3.3	16.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AMC1106E05DWVR	SOIC	DWV	8	1000	350.0	350.0	43.0
AMC1106M05DWVR	SOIC	DWV	8	1000	350.0	350.0	43.0

TUBE

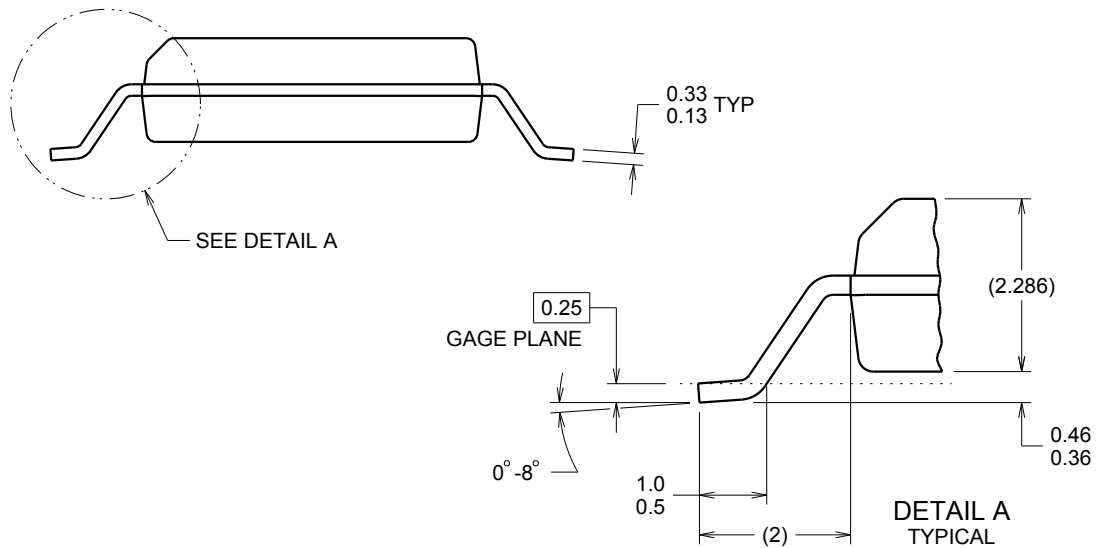


*All dimensions are nominal

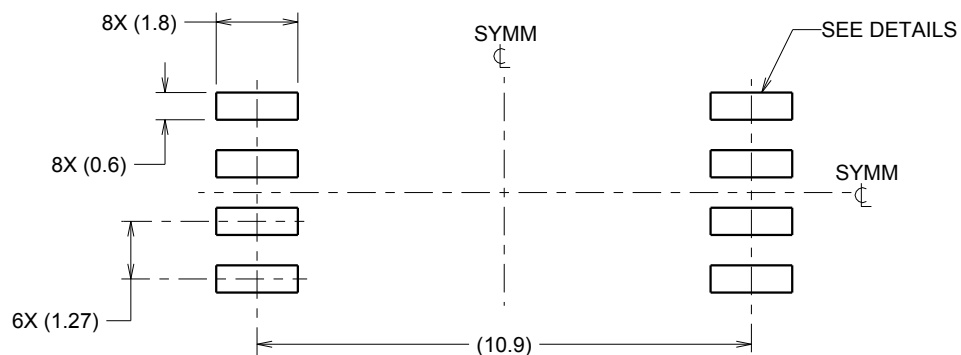
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
AMC1106E05DWV	DWV	SOIC	8	64	505.46	13.94	4826	6.6
AMC1106E05DWV.A	DWV	SOIC	8	64	505.46	13.94	4826	6.6
AMC1106E05DWV.B	DWV	SOIC	8	64	505.46	13.94	4826	6.6
AMC1106M05DWV	DWV	SOIC	8	64	505.46	13.94	4826	6.6
AMC1106M05DWV.A	DWV	SOIC	8	64	505.46	13.94	4826	6.6
AMC1106M05DWV.B	DWV	SOIC	8	64	505.46	13.94	4826	6.6

SOIC - 2.8 mm max height

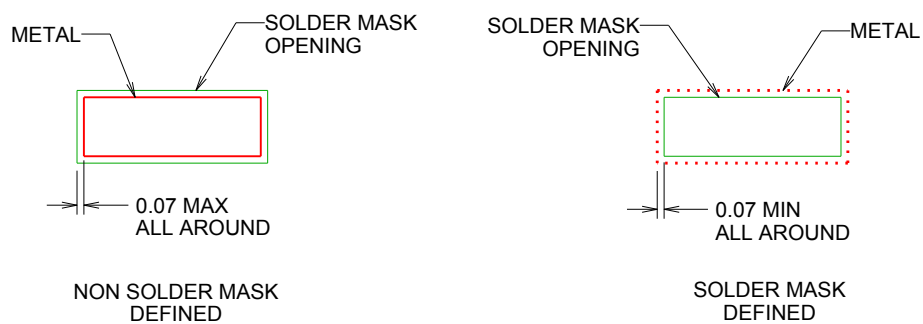
PIN 1 ID AREA
 11.5 ± 0.25 TYP
 5.95
 5.75
 NOTE 3
 4
 8
 6X 1.27
 2X 3.81
 5
 8X 0.51 / 0.31
 7.6
 7.4
 NOTE 4
 A
 B
 SEATING PLANE
 0.1 C
 2.8 MAX
 C
 A
 B



1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
9.1 mm NOMINAL CLEARANCE/CREEPAGE
SCALE:6X

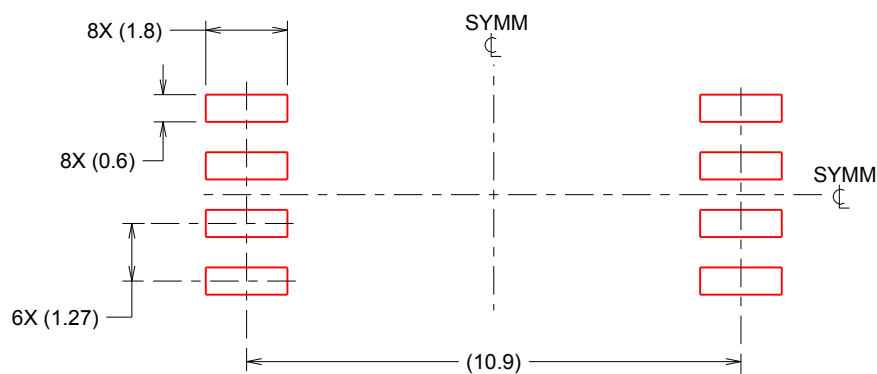


SOLDER MASK DETAILS

4218796/A 09/2013

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:6X

4218796/A 09/2013

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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